

TOSHIBA

27WLT56B

SERVICE MANUAL

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1. INTRODUCTION

27" TFT IDTV is a progressive TV control system with built-in **de-interlacer** and **scaler**. It uses a 1280*720 panel with 16:9 aspect ratio. The TV is capable of operation in PAL, SECAM, NTSC (playback) colour standards and multiple transmission standards as B/G, D/K, I/I', and L/L' including German and NICAM stereo. Sound system output is supplying 2x8W (10%THD) for stereo 8Ω speakers. The chassis is equipped with many inputs and outputs allowing it to be used as a center of a media system.

It supports following peripherals:

- 2 SCART's with all of them supporting full SCART features including RGB input
- 1 AV input. (CVBS+ Stereo Audio)
- 1 SVHS input
- 1 Stereo Headphone output
- 1 D-Sub 15 PC input
- 1 DVI input (supports HDCP)
- 1 Audio line out
- 1 Stereo audio input for PC/DVI
- 2 CI (Common Interface) slots

Other features include, 10 pg Teletext, Picture-In-Picture (PIP) , Picture-And-Picture (PAP) , Picture-And-Text (PAT).

2. TUNER

The tuners used in the design are combined VHF, UHF tuners suitable for CCIR systems B/G, H, L, L', I/I', and D/K. The tuning is available through the digitally controlled I²C bus (PLL). Below you will find info on one of the Tuners in use.

General description of UV1316:

The UV1316 tuner belongs to the UV 1300 family of tuners, which are designed to meet a wide range of applications. It is a combined VHF, UHF tuner suitable for CCIR systems B/G, H, L, L', I and I'. The low IF output impedance has been designed for direct drive of a wide variety of SAW filters with sufficient suppression of triple transient.

Features of UV1316:

- 1. Member of the UV1300 family small sized UHF/VHF tuners
- 2. Systems CCIR: B/G, H, L, L', I and I'; OIRT: D/K
- 3. Digitally controlled (PLL) tuning via I²C-bus
- 4. Off-air channels, S-cable channels and Hyperband
- 5. World standardised mechanical dimensions and world standard pinning
- 6. Compact size
- 7. Complies to "CENELEC EN55020" and "EN55013"

Pinning:

- | | | | |
|-----|-------------------------------------|---|-----------------------------|
| 1. | Gain control voltage (AGC) | : | 4.0V, Max: 4.5V |
| 2. | Tuning voltage | | |
| 3. | I ² C-bus address select | : | Max: 5.5V |
| 4. | I ² C-bus serial clock | : | Min:-0.3V, Max: 5.5V |
| 5. | I ² C-bus serial data | : | Min:-0.3V, Max: 5.5V |
| 6. | Not connected | | |
| 7. | PLL supply voltage | : | 5.0V, Min: 4.75V, Max: 5.5V |
| 8. | ADC input | | |
| 9. | Tuner supply voltage | : | 33V, Min: 30V, Max: 35V |
| 10. | Symmetrical IF output 1 | | |
| 11. | Symmetrical IF output 2 | | |

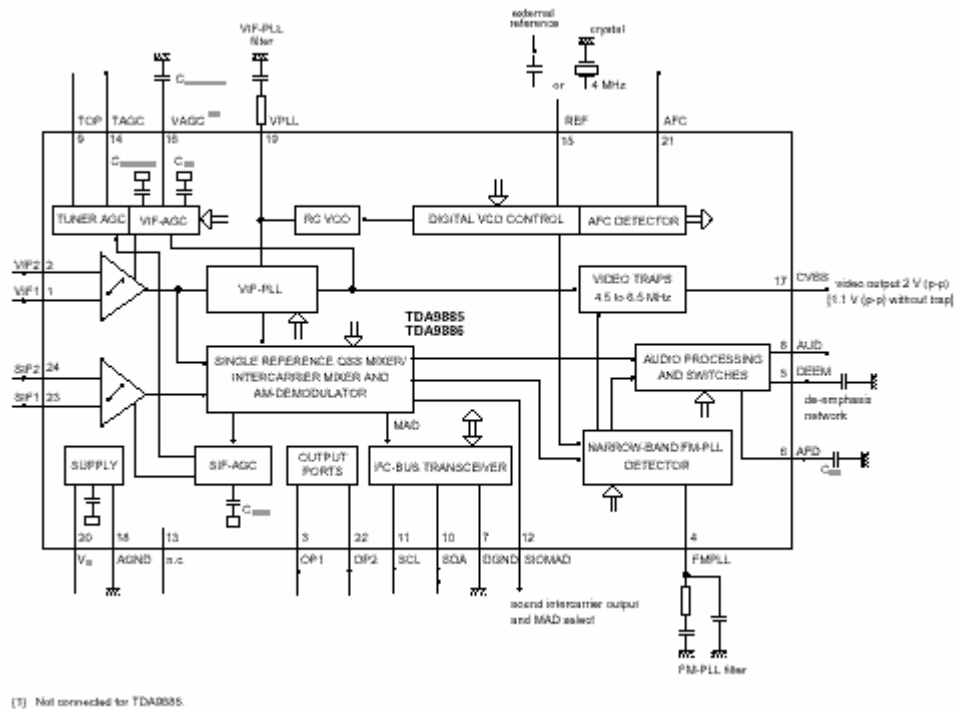
3. IF PART (TDA9886)

The TDA9886 is an alignment-free multistandard (PAL, SECAM and NTSC) vision and sound IF signal PLL. Both devices can be used for TV, VTR, PC and set-top box applications.

The following figure shows the simplified block diagram of the integrated circuit.

The integrated circuit comprises the following functional blocks:

VIF amplifier, Tuner and VIF-AGC, VIF-AGC detector, Frequency Phase-Locked Loop (FPLL) detector, VCO and divider, Digital acquisition help and AFC, Video demodulator and amplifier, Sound carrier trap, SIF amplifier, SIF-AGC detector, Single reference QSS mixer, AM demodulator, FM demodulator and acquisition help, Audio amplifier and mute time constant, I²C-bus transceivers and MAD (module address), Internal voltage stabilizer.



[3] Not connected for TDA9885.

4. MULTI STANDARD SOUND PROCESSOR

The MSP34x1G family of single-chip Multistandard Sound Processors covers the sound processing of all analog TV-Standards worldwide, as well as the NICAM digital sound standards. The full TV sound processing, starting with analog sound IF signal-in, down to processed analog AF-out, is performed on a single chip.

These TV sound processing ICs include versions for processing the multichannel television sound (MTS) signal conforming to the standard recommended by the Broadcast Television Systems Committee (BTSC). The DBX noise reduction, or alternatively, Micronas Noise Reduction (MNR) is performed alignment free. Other processed standards are the Japanese FM-FM multiplex standard (EIA-J) and the FM Stereo Radio standard.

Current ICs have to perform adjustment procedures in order to achieve good stereo separation for BTSC and EIA-J. The MSP34x1G has optimum stereo performance without any adjustments.

5. VIDEO SWITCH TEA6415

In case of three or more external sources are used, the video switch IC TEA6415 is used. The main function of this device is to switch 8 video-input sources on the 6 outputs.

Each output can be switched on only one of each input. On each input an alignment of the lowest level of the signal is made (bottom of sync. top for CVBS or black level for RGB signals).

Each nominal gain between any input and output is 6.5dB. For D2MAC or Chroma signal the alignment is switched off by forcing, with an external resistor bridge, 5VDC on the input. Each input can be used as a normal input or as a MAC or Chroma input (with external Resistor Bridge). All the switching possibilities are changed through the BUS. Driving 75ohm load needs an external resistor. It is possible to have the same input connected to several outputs.

6. AUDIO AMPLIFIER STAGE WITH TPA3002D2

The TPA3002D2 is a 9-W (per channel) efficient, Class-D audio amplifier for driving bridged-tied stereo speakers. The TPA3002D2 can drive stereo speakers as low as 8 Ω. The high efficiency of the TPA3002D2 eliminates the need for external heatsinks when playing music.

7. MAIN POWER SUPPLY (SMPS) AND POWER INTERFACE BOARD

The DC voltages required at various parts of the chassis and inverters are provided by an main power supply unit and power interface board. The main power supply unit is designed for 24V and 12V DC supply. Power interface board generates +12V for audio amplifier, 5V and 3.3V stand by voltage and 8V, 12V, 5V and 3V3 supplies for other different parts of the chassis.

An optocoupler is used to control the regulation of line voltage and stand-by power consumption. There is a regulation circuit in secondary side. During the switch on period of the transistor, energy is stored in the transformer. During the switch off period energy is fed to the load via secondary winding. By varying switch-on time of the power transistor, it controls each portion of energy transferred to the second side such that the output voltage remains nearly independent of load variations.

8. MICROCONTROLLER

The microprocessor is embedded inside PW181 chip which also handles scaling, frame rate conversion and OSD generation. The on-chip 16-bit microprocessor is a Turbo x86-compatible processor core with on-chip peripherals (timers, interrupt controller, 2-wire serial master/slave interface, UART, I/O ports, and more). Special peripherals such as Infrared (IR) pulse decoders and a digital pulse width modulator (PWM) are also included. There are two independent 2-wire serial master/slave interface modules that can be multiplexed to control up to five 2-wire serial ports. The slave 2-wire interface is designed for HDCP use only (and requires the use of HDCP Image Processors). On-chip RAM of up to 64 Kbytes is available. A complete microprocessor system can be implemented simply by adding external ROM. The on-chip processor can be disabled to allow external processor control of all internal functions.

9. SERIAL ACCESS CMOS 4K x 8 (32K bit) EEPROM 24C32A

The Microchip Technology Inc. 24C32A is a 4K x 8 (32K bit) Serial Electrically Erasable PROM. It has been developed for advanced, low power applications such as personal communications or data acquisition. The 24C32A also has a page-write capability of up to 32 bytes of data. The 24C32A is capable of both random and sequential reads up to the 32K boundary. Functional address lines allow up to eight 24C32A devices on the same bus, for up to 256K bits address space. Advanced CMOS technology and broad voltage range make this device ideal for low-power/low-voltage, non-volatile code and data applications.

10. CLASS AB STEREO HEADPHONE DRIVER TDA1308

The TDA1308 is an integrated class AB stereo headphone driver contained in a DIP8 plastic package. The device is fabricated in a 1 mm CMOS process and has been primarily developed for portable digital audio applications.

11. SAW FILTERS

K9656M:

Standard:

- B/G
- D/K
- I
- L/L'

Features

- TV IF audio filter with two channels
- Channel 1 (L') with one pass band for sound carriers at 40,40 MHz (L') and 39,75 MHz (L'- NICAM)
- Channel 2 (B/G,D/K,L,I) with one pass band for sound carriers between 32,35 MHz and 33,40 MHz

Terminals

- Tinned CuFe alloy

Pin configuration

- 1 Input
- 2 Switching input
- 3 Chip carrier - ground
- 4 Output
- 5 Output

K3953M:**Standard:**

- B/G
- D/K
- I
- L/L'

Features

TV IF video filter with Nyquist slopes at 33,90 MHz and 38,90 MHz
Constant group delay
Suitable for CENELEC EN 55020

Terminals

Tinned CuFe alloy

Pin configuration

- 1 Input
- 2 Input - ground
- 3 Chip carrier - ground
- 4 Output
- 5 Output

12. IC DESCRIPTIONS AND INTERNAL BLOCK DIAGRAM

TDA9886
TEA6415C
24C32
SAA5264
LM317T
ST24LC21
TLC7733
74LVC257A
74LVC14A
LM1117
IRF7314
IRF7316
MC34063A
LM2576
DS90C385
MSP3411G
TPA3002D
TDA1308
PI5V330
MST9883
SAA7118E
TPS72501
TSOP1136
PCF8591
PW1231
PW181
SIL1169
SDRAM 4M x 16 (MT48LC4M16A2TG-75)
FLASH
ASM3P2814
74LX1G86
74HCT4053

12.1. TDA9886

12.1.1. General Description

The TDA9885 is an alignment-free single standard (without positive modulation) vision and sound IF signal PLL.

12.1.2. Features

- 5 V supply voltage
- Gain controlled wide-band Vision Intermediate Frequency (VIF) amplifier (AC-coupled)
- Multistandard true synchronous demodulation with active carrier regeneration (very linear demodulation, good intermodulation figures, reduced harmonics, excellent pulse response)
- Gated phase detector for L/L accent standard
- Fully integrated VIF Voltage Controlled Oscillator (VCO), alignment-free; frequencies switchable for all negative and positive modulated standards via I²C-bus
- Digital acquisition help, VIF frequencies of 33.4, 33.9, 38.0, 38.9, 45.75 and 58.75 MHz
- 4 MHz reference frequency input [signal from Phase-Locked Loop (PLL) tuning system] or operating as crystal oscillator
- VIF Automatic Gain Control (AGC) detector for gain control, operating as peak sync detector for negative modulated signals and as a peak white detector for positive modulated signals
- Precise fully digital Automatic Frequency Control (AFC) detector with 4-bit digital-to-analog converter; AFC bits via I²C -bus readable
- TakeOver Point (TOP) adjustable via I²C-bus or alternatively with potentiometer
- Fully integrated sound carrier trap for 4.5, 5.5, 6.0 and 6.5 MHz, controlled by FM-PLL oscillator
- Sound IF (SIF) input for single reference Quasi Split Sound (QSS) mode (PLL controlled)
- SIF AGC for gain controlled SIF amplifier; single reference QSS mixer able to operate in high performance single reference QSS mode and in intercarrier mode, switchable via I²C-bus
- AM demodulator without extra reference circuit
- Alignment-free selective FM-PLL demodulator with high linearity and low noise
- I²C-bus control for all functions
- I²C-bus transceiver with pin programmable Module Address (MAD).

12.1.3. Pinning

SYMBOL	PIN	DESCRIPTION
VIF1	1	VIF differential input 1
VIF2	2	VIF differential input 2
OP1	3	output 1 (open-collector)
FMPLL	4	FM-PLL for loop filter
DEEM	5	de-emphasis output for capacitor
AFD	6	AF decoupling input for capacitor
DGND	7	digital ground
AUD	8	audio output
TOP	9	tuner AGC TakeOver Point (TOP)
SDA	10	I ² C-bus data input/output
SCL	11	I ² C-bus clock input
SIOMA	12	sound intercarrier output and MAD select
n.c.	13	not connected
TAGC	14	tuner AGC output
REF	15	4 MHz crystal or reference input
VAGC	16	VIF-AGC for capacitor; note 1
CVBS	17	video output
AGND	18	analog ground
VPLL	19	VIF-PLL for loop filter
V _P	20	supply voltage (+5 V)
AFC	21	AFC output

OP2	22	output 2 (open-collector)
SIF1	23	SIF differential input 1
SIF2	24	SIF differential input 2

12.2. TEA6415C

12.2.1. General Description

The main function of the IC is to switch 8 video input sources on 6 outputs. Each output can be switched on only one of each input. On each input an alignment of the lowest level of the signal is made (bottom of synch. top for CVBS or black level for RGB signals). Each nominal gain between any input and output is 6.5dB. For D2MAC or Chroma signal the alignment is switched off by forcing, with an external resistor bridge, 5 V_{DC} on the input. Each input can be used as a normal input or as a MAC or Chroma input (with external resistor bridge). All the switching possibilities are changed through the BUS. Driving 75Ω load needs an external transistor. It is possible to have the same input connected to several outputs. The starting configuration upon power on (power supply: 0 to 10V) is undetermined. In this case, 6 words of 16 bits are necessary to determine one configuration. In other case, 1 word of 16 bits is necessary to determine one configuration.

12.2.2. Features

- 20MHz Bandwidth
- Cascadable with another TEA6415C (Internal address can be changed by pin 7 voltage)
- 8 Inputs (CVBS, RGB, MAC, CHROMA,...)
- 6 Outputs
- Possibility of MAC or chroma signal for each input by switching-off the clamp with an external resistor bridge
- Bus controlled
- 6.5dB gain between any input and output
- 55dB crosstalk at 5mHz
- Fully ESD protected

12.2.3. Pinning

1.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
2.	Data	:	Low level	: -0.3V Max: 1.5V,
			High level	: 3.0V Max : Vcc+0.5V
3.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max : 3mA
4.	Clock	:	Low level	: -0.3V Max: 1.5V,
			High level	: 3.0V Max : Vcc+0.5V
5.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
6.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
7.	Prog			
8.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
9.	Vcc	:	12V	
10.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
11.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
12.	Ground			
13.	Output	:	5.5Vpp,	Min : 4.5Vpp
14.	Output	:	5.5Vpp,	Min : 4.5Vpp
15.	Output	:	5.5Vpp,	Min : 4.5Vpp
16.	Output	:	5.5Vpp,	Min : 4.5Vpp
17.	Output	:	5.5Vpp,	Min : 4.5Vpp
18.	Output	:	5.5Vpp,	Min : 4.5Vpp
19.	Ground			
20.	Input	:	Max	: 2Vpp, Input Current : 1mA, Max : 3mA

12.3. 24C32A

12.3.1. Features

- Voltage operating range: 4.5V to 5.5V
- Maximum write current 3 mA at 5.5V
- Standby current 1 mA typical at 5.0V
- 2-wire serial interface bus, I²C™ compatible
- 100 kHz and 400 kHz compatibility
- Self-timed ERASE and WRITE cycles
- Power on/off data protection circuitry
- Hardware write protect
- 1,000,000 Erase/Write cycles guaranteed
- 32-byte page or byte write modes available
- Schmitt trigger filtered inputs for noise suppression
- Output slope control to eliminate ground bounce
- 2 ms typical write cycle time, byte or page
- Up to eight devices may be connected to the same bus for up to 256K bits total memory
- Electrostatic discharge protection > 4000V
- Data retention > 200 years
- 8-pin PDIP and SOIC packages
- Temperature ranges
- Commercial (C): 0°C to 70°C
- Industrial (I): -40°C to +85°C
- Automotive (E): -40°C to +125°C

12.3.2. Description

The Microchip Technology Inc. 24C32A is a 4K x 8 (32K bit) Serial Electrically Erasable PROM. It has been developed for advanced, low power applications such as personal communications or data acquisition. The 24C32A also has a page-write capability of up to 32 bytes of data. The 24C32A is capable of both random and sequential reads up to the 32K boundary. Functional address lines allow up to eight 24C32A devices on the same bus, for up to 256K bits address space. Advanced CMOS technology and broad voltage range make this device ideal for low-power/low-voltage, non-volatile code and data applications. The 24C32A is available in the standard 8-pin plastic DIP and both 150 mil and 200 mil SOIC packaging.

12.3.3. Pin Function table

Name	Function
A0, A1, A2	User Configurable Chip Selects
V _{ss}	Ground
SDA	Serial Address/Data I/O
SCL	Serial Clock
WP	Write Protect Input
V _{cc}	+4.5V to 5.5V Power Supply

12.3.4. Functional Descriptions

The 24C32A supports a Bi-directional 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as transmitter, and a device receiving data as receiver. The bus must be controlled by a master device which generates the Serial Clock (SCL), controls the bus access, and generates the START and STOP conditions, while the 24C32A works as slave. Both master and slave can operate as transmitter or receiver but the master device determines which mode is activated.

12.4. SAA5264

12.4.1. Features

The following features apply to both SAA5264 and SAA5265:

- Complete 625 line teletext decoder in one chip reduces printed circuit board area and cost
- Automatic detection of transmitted fasttext links or service information (packet 8/30)
- On-Screen Display (OSD) for user interface menus using teletext and dedicated menu icons
- Video Programming System (VPS) decoding
- Wide Screen Signalling (WSS) decoding
- Pan-European, Cyrillic, Greek/Turkish and French/Arabic character sets in each chip
- High-level command interface via I²C-bus gives easy control with a low software overhead
- High-level command interface is backward compatible to Stand-Alone Fasttext And Remote Interface (SAFARI)
- 625 and 525 line display
- RGB interface to standard colour decoder ICs, current source
- Versatile 8-bit open-drain Input/Output (I/O) expander, 5 V tolerant
- Single 12 MHz crystal oscillator
- 3.3 V supply voltage.

SAA5264 features

- Automatic detection of transmitted pages to be selected by page up and page down
- 8 Page fasttext decoder
- Table Of Pages (TOP) decoder with Basic Top Table (BTT) and Additional Information Tables (AITs)
- 4 Page user-defined list mode.

12.4.2. General Description

The SAA5264 is a single-chip ten page 625-line World System Teletext decoder with a high-level command interface, and is SAFARI compatible.

The device is designed to minimize the overall system cost, due to the high-level command interface offering the benefit of a low software overhead in the TV microcontroller.

The SAA5264 has the following functionality:

- 10 page teletext decoder with OSD, Fasttext, TOP, default and list acquisition modes
- Automatic channel installation support
- Closed caption acquisition and display
- Violence Chip (VChip) support.

12.4.3. Pin Connections and Short Descriptions

SYMBOL	PIN	TYPE	DESCRIPTION
Port 2: 8-bit programmable bidirectional port with alternative functions			
P2.0/PWM	1	I/O	output for 14-bit high precision Pulse Width Modulator (PWM)
P2.1/PWM0	2	I/O	outputs for 6-bit PWMs 0 to 6
P2.2/PWM1	3	I/O	
P2.3/PWM2	4	I/O	
P2.4/PWM3	5	I/O	
P2.5/PWM4	6	I/O	
P2.6/PWM5	7	I/O	
P2.7/PWM6	8	I/O	
Port 3: 8-bit programmable bidirectional port with alternative functions			
P3.0/ADC0	9	I/O	inputs for the software Analog-to-Digital-Converter (ADC) facility
P3.1/ADC1	10	I/O	

P3.2/ADC2	11	I/O	
P3.3/ADC3	12	I/O	
P3.4/PWM7	30	I/O	output for 6-bit PWM7
V _{SSC}	13	I/O	core ground
Port 0: 8-bit programmable bidirectional port			
SCL(NVRAM)	14	I	I ² C-bus Serial Clock input to Non-Volatile RAM
SDA(NVRAM)	15	I/O	I ² C-bus Serial Data input/output (Non-Volatile RAM)
P0.2	16	I/O	input/output for general use
P0.3	17	I/O	input/output for general use
P0.4	18	I/O	input/output for general use
P0.5	19	I/O	8 mA current sinking capability for direct drive of Light Emitting Diodes (LEDs)
P0.6	20	I/O	
P0.7	21	I/O	input/output for general use
V _{SSA}	22	-	analog ground
CVBS0	23	I	Composite Video Baseband Signal (CVBS) input; a positive-going 1V
CVBS1	24	I	(peak-to-peak) input is required; connected via a 100 nF capacitor
SYNC_FILTER	25	I	sync-pulse-filter input for CVBS; this pin should be connected to V _{SSA} via a 100 nF capacitor
IREF	26	I	reference current input for analog circuits; for correct operation a 24 kΩ resistor should be connected to V _{SSA}
FRAME	27	O	Frame de-interlace output synchronized with the VSYNC pulse to produce a non-interlaced display by adjustment of the vertical deflection circuits
TEST	28	I	not available; connect this pin to V _{SSA}
COR	29	O	contrast reduction: open-drain, active LOW output which allows selective contrast reduction of the TV picture to enhance a mixed mode display
	30	I/O	P3.4/PWM7 (described above)
V _{DDA}	31	-	analog supply voltage (3.3 V)
B	32	O	Blue colour information pixel rate output
G	33	O	Green colour information pixel rate output
R	34	O	Red colour information pixel rate output
VDS	35	O	video/data switch push-pull output for pixel rate fast blanking
HSYNC	36	I	horizontal sync pulse input: Schmitt triggered for a Transistor Transistor Level (TTL) version; the polarity of this pulse is programmable by register bit TXT1.H POLARITY
VSYNC	37	I	vertical sync pulse input; Schmitt triggered for a TTL version; the polarity of this pulse is programmable by register bit TXT1.V POLARITY
V _{SSP}	38	-	periphery ground
V _{DDC}	39	-	core supply voltage (+3.3 V)
OSCGND	40	-*	crystal oscillator ground
XTALIN	41	I	12 MHz crystal oscillator input
XTALOUT	42	O	12 MHz crystal oscillator output
RESET	43	I	reset input; if this pin is HIGH for at least 2 machine cycles (24 oscillator periods) while the oscillator is running, the device resets; this pin should be connected to V _{DDP} via a capacitor
V _{DDP}	44	-	periphery supply voltage (+3.3 V)
Port 1: 8-bit programmable bidirectional port			
P1.0	45	I/O	input/output for general use
P1.1	46	I/O	input/output for general use
P1.2	47	I/O	input/output for general use
P1.3	48	I/O	input/output for general use
SCL	49	I	I ² C-bus Serial Clock input from application

SDA	50	I/O	I ² C-bus Serial Data input from (application)
P1.4	51	I/O	input/output for general use
P1.5	52	I/O	input/output for general use

12.5. LM317

12.5.1. General Description

The LM117/LM217/LM317 are monolithic integrated circuit in TO-220, ISOWATT220, TO-3 and D 2 PAK packages intended for use as positive adjustable voltage regulators.

They are designed to supply more than 1.5A of load current with an output voltage adjustable over a 1.2 to 37V range.

The nominal output voltage is selected by means of only a resistive divider, making the device exceptionally easy to use and eliminating the stocking of many fixed regulators.

12.5.2. Features

- Output voltage range : 1.2 To 37V
- Output current In excess of 1.5A
- 0.1% Line and Load Regulation
- Floating Operation for High Voltages
- Complete Series of Protections : Current Limiting, Thermal Shutdown And Soa Control

12.6. ST24LC21

12.6.1. Description

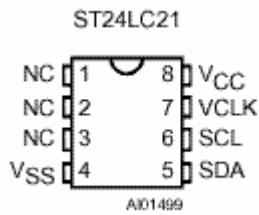
The ST24LC21 is a 1K bit electrically erasable programmable memory (EEPROM), organized by 8 bits. This device can operate in two modes: Transmit Only mode and I²C bidirectional mode. When powered, the device is in Transmit Only mode with EEPROM data clocked out from the rising edge of the signal applied on VCLK. The device will switch to the I²C bidirectional mode upon the falling edge of the signal applied on SCL pin. The ST24LC21 can not switch from the I²C bidirectional mode to the Transmit Only mode (except when the power supply is removed). The device operates with a power supply value as low as 2.5V. Both Plastic Dual-in-Line and Plastic Small Outline packages are available.

12.6.2. Features

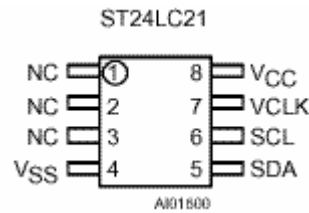
- 1 million Erase/Write cycles
- 40 years data retention
- 2.5V To 5.5V single supply voltage
- 400k Hz compatibility over the full range of supply voltage
- Two wire serial interface I²C bus compatible
- Page Write (Up To 8 Bytes)
- Byte, random and sequential read modes
- Self timed programming cycle
- Automatic address incrementing
- Enhanced ESD/Latch up
- Performances

12.6.3. Pin connections

DIP Pin connections



CO Pin connections



NC: Not connected

Signal names

SDA	Serial data Address Input/Output
SCL	Serial Clock (I ² C mode)
V _{cc}	Supply voltage
V _{ss}	Ground
VCLK	Clock transmit only mode

12.7. TLC7733

12.7.1. Description

The TLC77xx family of micropower supply voltage supervisors are designed for reset control, primarily in microcomputer and microprocessor systems.

During power-on, RESET is asserted when V_{DD} reaches 1 V. After minimum V_{DD} (. 2 V) is established, the circuit monitors SENSE voltage and keeps the reset outputs active as long as SENSE voltage (V_{I(SENSE)}) remains below the threshold voltage. An internal timer delays return of the output to the inactive state to ensure proper system reset. The delay time, t_d, is determined by an external capacitor:

$$t_d = 2.1 \times 10^4 \times C_T$$

where

C_T is in farads

t_d is in seconds

The TLC77xx has a fixed SENSE threshold voltage set by an internal voltage divider. When SENSE voltage drops below the threshold voltage, the outputs become active and stay in that state until SENSE voltage returns above threshold voltage and the delay time, t_d, has expired.

In addition to the power-on-reset and undervoltage-supervisor function, the TLC77xx adds power-down control support for static RAM. When CONTROL is tied to GND, RESET will act as active high. The voltage monitor contains additional logic intended for control of static memories with battery backup during power failure. By driving the chip select (CS) of the memory circuit with the RESET output of the TLC77xx and with the CONTROL driven by the memory bank select signal (CSH1) of the microprocessor (see Figure 10), the memory circuit is automatically disabled during a power loss. (In this application the TLC77xx power has to be supplied by the battery.)

The TLC77xxQ is characterized for operation over a temperature range of –40°C to 125°C, and the TLC77xxL is characterized for operation over a temperature range of –40°C to 85°C.

12.8. 74LVC257A

12.8.1. Features

Wide supply voltage range of 1.2 to 3.6 V
In accordance with JEDEC standard no. 8-1A
CMOS lower power consumption
Direct interface with TTL levels
Output drive capability 50 _ transmission lines at 85°C
5 Volt tolerant inputs/outputs, for interfacing with 5 Volt logic

12.8.2. Description

The 74LVC257A is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-State operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC257A is a quad 2-input multiplexer with 3-state outputs, which select 4 bits of data from two sources and are controlled by a common data select input (S). The data inputs from source 0 (1I 0 to 4I 0) are selected when input S is LOW and the data inputs from source 1 (1I 1 to 4I 1) are selected when S is HIGH. Data appears at the outputs (1Y to 4Y) in true (non-inverting) form from the selected inputs. The 74LVC257A is the logic implementation of a 4-pole, 2-position switch, where the position of the switch is determined by the logic levels applied to S. The outputs are forced to a high impedance OFF-state when OE is HIGH.

12.8.3. Pin Description

PIN NUMBER	SYMBOL	DESCRIPTION
1	S	Common data select input
2, 5, 11, 14	1 ₀ to 4 ₀	Data inputs from source 0
3, 6, 10, 13	1 ₁ to 4 ₁	Data outputs from source 1
4,7,9,12	1Y to 4Y	3-State multiplexer outputs
8	GND	Ground (0V)
15	OE	3-State output enable input (active LOW)
16	V _{cc}	Positive supply voltage

12.9. 74LVC14A

12.9.1. Features

- Wide supply voltage range of 1.2 to 3.6 V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels

12.9.2. Applications

- Wave and pulse shapers for highly noisy environments
- Astable multivibrators
- Monostable multivibrators

12.9.3. Description

The 74LVC14A is a high-performance, low power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V environment.

The 74LVC14A provides six inverting buffers with Schmitt-trigger action. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

12.9.4. Pin Description

PIN NUMBER	SYMBOL	DESCRIPTION
1, 3, 5, 9, 11, 13	1A – 6A	Data inputs
2, 4, 6, 8, 10, 12	1Y – 6Y	Data outputs
7	GND	Ground (0V)
14	V _{CC}	Positive supply voltage

12.10. LM1117

12.10.1. General Description

The LM1117 is a series of low dropout voltage regulators with a dropout of 1.2V at 800mA of load current. It has the same pin-out as National Semiconductor's industry standard LM317. The LM1117 is available in an adjustable version, which can set the output voltage from 1.25V to 13.8V with only two external resistors. In addition, it is also available in five fixed voltages, 1.8V, 2.5V, 2.85V, 3.3V, and 5V. The LM1117 offers current limiting and thermal shutdown. Its circuit includes a zener trimmed bandgap reference to assure output voltage accuracy to within $\pm 1\%$. The LM1117 series is available in SOT-223, TO-220, and TO-252 D-PAK packages. A minimum of 10 μ F tantalum capacitor is required at the output to improve the transient response and stability.

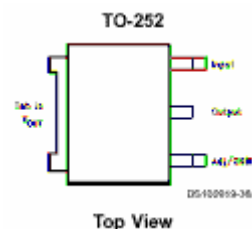
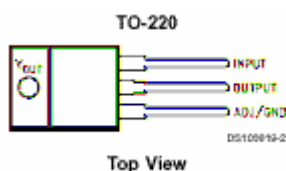
12.10.2. Features

- Available in 1.8V, 2.5V, 2.85V, 3.3V, 5V, and Adjustable Versions
- Space Saving SOT-223 Package
- Current Limiting and Thermal Protection
- Output Current 800mA
- Line Regulation 0.2% (Max)
- Load Regulation 0.4% (Max)
- Temperature Range
 - LM1117 0°C to 125°C
 - LM1117I -40°C to 125°C

12.10.3. Applications

- 2.85V Model for SCSI-2 Active Termination
- Post Regulator for Switching DC/DC Converter
- High Efficiency Linear Regulators
- Battery Charger
- Battery Powered Instrumentation

12.10.4. Connection Diagrams



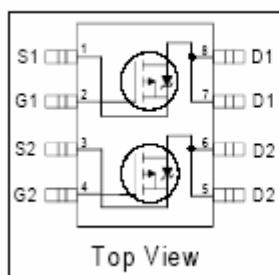
12.11. IRF7314- IRF7316

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics and multiple-die capability making it ideal in a variety of power applications. With these improvements, multiple devices can be used in an application with dramatically reduced board space. The package is designed for vapor phase, infra red, or wave soldering techniques.

IRF7314

HEXFET® Power MOSFET



$V_{DS} = -20V$
$R_{DS(on)} = 0.058\Omega$

IRF7316

$V_{DS} = -30V$
$R_{DS(on)} = 0.058\Omega$

Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted) (IRF7314)

	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I	-5.3	A
$T_A = 25^\circ C$		-4.3	
$T_A = 70^\circ C$		-4.3	
Pulsed Drain Current	I_{DM}	-21	
Continuous Source Current (Diode Conduction)	I_S	-2.5	
Maximum Power Dissipation	P	2.0	W
$T_A = 25^\circ C$		1.3	
Single Pulse Avalanche Energy	EAS	150	mJ
Avalanche Current	I_{AR}	-2.9	A
Repetitive Avalanche Energy	EAR	0.20	mJ
Peak Diode Recovery dv/dt	dv/dt	-5.0	V/ ns
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to + 150	$^\circ C$

Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted) (IRF7316)

	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I	-4.9	A
$T_A = 25^\circ C$		-3.9	
$T_A = 70^\circ C$		-3.9	
Pulsed Drain Current	I_{DM}	-30	
Continuous Source Current (Diode Conduction)	I_S	-2.5	
Maximum Power Dissipation	P	2.0	W
$T_A = 25^\circ C$		1.3	
$T_A = 70^\circ C$		1.3	
Single Pulse Avalanche Energy	EAS	140	mJ
Avalanche Current	I_{AR}	-2.8	A
Repetitive Avalanche Energy	EAR	0.20	mJ
Peak Diode Recovery dv/dt	dv/dt	-5.0	V/ ns

Junction and Storage Temperature Range	T _J , T _{STG}	-55 to + 150	°C
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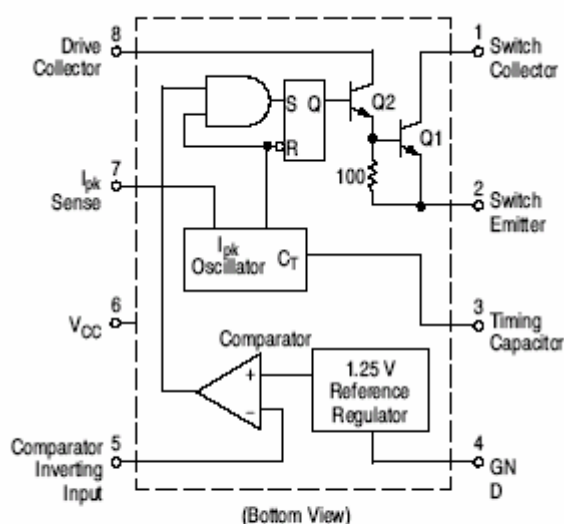
12.12. MC34063A

1.5 A, Step-Up/Down/Inverting Switching Regulators

The MC34063A Series is a monolithic control circuit containing the primary functions required for DC-to-DC converters. These devices consist of an internal temperature compensated reference, comparator, controlled duty cycle oscillator with an active current limit circuit, driver and high current output switch. This series was specifically designed to be incorporated in Step-Down and Step-Up and Voltage-Inverting applications with a minimum number of external components. Refer to Application Notes AN920A/D and AN954/D for additional design information.

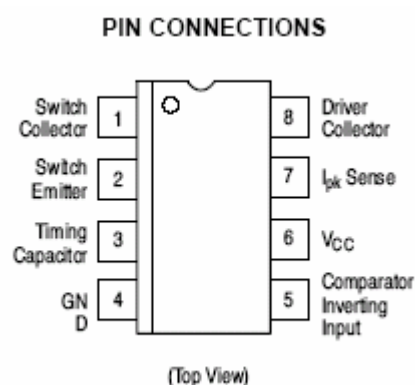
Features:

- Operation from 3.0 V to 40 V Input
- Low Standby Current
- Current Limiting
- Output Switch Current to 1.5 A
- Output Voltage Adjustable
- Frequency Operation to 100 kHz
- Precision 2% Reference
- Pb-Free Packages are Available



This device contains 51 active transistors.

Figure 1. Representative Schematic Diagram



MC34063A, MC33063A, NCV33063A

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage	V_{CC}	40	Vdc
Comparator Input Voltage Range	V_{IR}	-0.3 to +40	Vdc
Switch Collector Voltage	$V_{C(switch)}$	40	Vdc
Switch Emitter Voltage ($V_{Pin\ 1} = 40\text{ V}$)	$V_{E(switch)}$	40	Vdc
Switch Collector to Emitter Voltage	$V_{CE(switch)}$	40	Vdc
Driver Collector Voltage	$V_{C(driver)}$	40	Vdc
Driver Collector Current (Note 1)	$I_{C(driver)}$	100	mA
Switch Current	I_{SW}	1.5	A
Power Dissipation and Thermal Characteristics			
Plastic Package, P, P1 Suffix			
$T_A = 25^\circ\text{C}$	P_D	1.25	W
Thermal Resistance	$R_{\theta JA}$	100	$^\circ\text{C/W}$
SOIC Package, D Suffix			
$T_A = 25^\circ\text{C}$	P_D	625	mW
Thermal Resistance	$R_{\theta JA}$	160	$^\circ\text{C/W}$
Operating Junction Temperature	T_J	+150	$^\circ\text{C}$
Operating Ambient Temperature Range	T_A		$^\circ\text{C}$
MC34063A		0 to +70	
MC33063AV, NCV33063A		-40 to +125	
MC33063A		-40 to +85	
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Maximum package power dissipation limits must be observed.
2. ESD data available upon request.
3. NCV prefix is for automotive and other applications requiring site and change control.

12.13. LM2576- 52kHz Simple 3A Buck Regulator

12.13.1. General Description

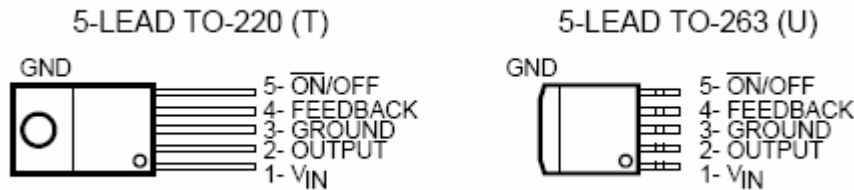
The LM2576 series of monolithic integrated circuits provide all the active functions for a step-down (buck) switching regulator. Fixed versions are available with a 3.3V, 5V, or 12V fixed output. Adjustable versions have an output voltage range from 1.23V to 37V. Both versions are capable of driving a 3A load with excellent line and load regulation. These regulators are simple to use because they require a minimum number of external components and include internal frequency compensation and a fixed-frequency oscillator. The LM2576 series offers a high efficiency replacement for popular three-terminal adjustable linear regulators. It substantially reduces the size of the heat sink, and in many cases no heat sink is required. A standard series of inductors available from several different manufacturers are ideal for use with the LM2576 series. This feature greatly simplifies the design of switch-mode power supplies. The feedback voltage is guaranteed to $\pm 2\%$ tolerance for adjustable versions, and the output voltage is guaranteed to $\pm 3\%$ for fixed versions, within specified input voltages and output load conditions. The oscillator frequency is guaranteed to $\pm 10\%$. External shutdown is included, featuring less than 200 μA standby current. The output switch includes cycle-by-cycle current limiting and thermal shutdown for full protection under fault conditions.

12.13.2. Features

- 3.3V, 5V, 12V, and adjustable output versions
- Voltage over specified line and load conditions:
Fixed version: $\pm 3\%$ max. output voltage
Adjustable version: $\pm 2\%$ max. feedback voltage
- Guaranteed 3A output current
- Wide input voltage range:
4V to 40V

- Wide output voltage range
1.23V to 37V
- Requires only 4 external components
- 52kHz fixed frequency internal oscillator
- Low power standby mode I_Q typically < 200 (A
- 80% efficiency (adjustable version typically > 80%)
- Uses readily available standard inductors
- Thermal shutdown and current limit protection
- 100% electrical thermal limit burn-in

12.13.3. Pin Configurations



Absolute Maximum Ratings (Note 1)

Maximum Supply Voltage	45V
ON/OFF Pin Input Voltage	$-0.3V \leq V \leq +40V$
Output Voltage to Ground (Steady State)	-1V
Power Dissipation	Internally Limited
Storage Temperature Range	-65°C to +150°C
Minimum ESD Rating	
C = 100pF, R = 1.5kΩ	2 kV
FB Pin	1 kV
Lead Temperature (soldering, 10 sec.)	260°C
Maximum Junction Temperature	150°C

12.14. DS90C385

12.14.1. General Description

The DS90C385 transmitter converts 28 bits of LVCMOS/LVTTL data into four LVDS (Low Voltage Differential Signaling) data streams. A phase-locked transmit clock is transmitted in parallel with the data streams over a fifth LVDS link.

Every cycle of the transmit clock 28 bits of input data are sampled and transmitted. At a transmit clock frequency of 85 MHz, 24 bits of RGB data and 3 bits of LCD timing and control data (FPLINE, FPFRAME, DRDY) are transmitted at a rate of 595 Mbps per LVDS data channel. Using an 85 MHz clock, the data throughput is 297.5 Mbytes/sec. Also available is the DS90C365 that converts 21 bits of LVCMOS/LVTTL data into three LVDS (Low Voltage Differential Signaling) data streams. Both transmitters can be programmed for Rising edge strobe or falling edge strobe through a dedicated pin. A Rising edge or Falling edge strobe transmitter will interoperate with a Falling edge strobe Receiver (DS90CF386/DS90CF366) without any translation logic.

The DS90C385 is also offered in a 64 ball, 0.8mm fine pitch ball grid array (FBGA) package which provides a 44 % reduction in PCB footprint compared to the TSSOP package. This chipset is an ideal means to solve EMI and cable size problems associated with wide, high-speed TTL interfaces.

12.14.2. Features

- 20 to 85 MHz shift clock support
- Best-in-Class Set & Hold Times on TxINPUTs
- Tx power consumption <130 mW (typ) @85MHz Grayscale
- Tx Power-down mode <200μW (max)
- Supports VGA, SVGA, XGA and Dual Pixel SXGA.
- Narrow bus reduces cable size and cost

- Up to 2.38 Gbps throughput
- Up to 297.5 Megabytes/sec bandwidth
- 345 mV (typ) swing LVDS devices for low EMI
- PLL requires no external components
- Compatible with TIA/EIA-644 LVDS standard
- Low profile 56-lead or 48-lead TSSOP package
- DS90C385 also available in a 64 ball, 0.8mm fine pitch ball grid array (FBGA) package

12.14.3. Pin Description

DS90C385 MTD56 (TSSOP) Package Pin Description-FPD Link Transmitter

Pin Name	I/O	No.	Description
TxIN	I	28	TTL level input. This includes: 8 Red, 8 Green, 8 Blue, and 4 control lines —FPLINE, FPFRAME and DRDY (also referred to as HSYNC, VSYNC, Data Enable).
TxOUT+	O	4	Positive LVDS differential data output.
TxOUT-	O	4	Negative LVDS differential data output.
TxCLKIN	I	1	TTL level clock input. Pin name TxCLK IN.
R_FB	I	1	Programmable strobe select
TxCLK OUT+	O	1	Positive LVDS differential clock output.
TxCLK OUT-	O	1	Negative LVDS differential clock output.
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down.
Vcc	I	3	Power supply pins for TTL inputs.
GND	I	4	Ground pins for TTL inputs.
PLL Vcc	I	1	Power supply pin for PLL.
PLL GND	I	2	Ground pins for PLL.
LVDS Vcc	I	1	Power supply pin for LVDS outputs.
LVDS GND	I	3	Ground pins for LVDS outputs.
Pin Name	I/O	No.	Description
TxIN	I	28	TTL level input.
TxOUT+	O	4	Positive LVDS differential data output.
TxOUT-	O	4	Negative LVDS differential data output.
TxCLKIN	I	1	TTL level clock input. The rising edge acts as data strobe. Pin name TxCLK IN.
R_FB	I	1	Programmable strobe select. HIGH = rising edge, LOW = falling edge.
TxCLK OUT+	O	1	Positive LVDS differential clock output.
TxCLK OUT-	O	1	Negative LVDS differential clock output.
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down.
Vcc	I	3	Power supply pins for TTL inputs.
GND	I	5	Ground pins for TTL inputs.
PLL Vcc	I	1	Power supply pin for PLL.
PLL GND	I	2	Ground pins for PLL.
LVDS Vcc	I	2	Power supply pin for LVDS outputs.
LVDS GND	I	4	Ground pins for LVDS outputs.
NC		6	Pins not connected.

12.15. MSP34X1G

MSP3411G

Multistandard Sound Processor Family

12.15.1. Introduction

The MSP 34x1G family of single-chip Multistandard Sound Processors covers the sound processing of all analog TV-Standards worldwide, as well as the NICAM digital sound standards. The full TV sound processing, starting with analog sound IF signal-in, down to processed analog AF-out, is performed on a single chip. Figure shows a simplified functional block diagram of the MSP 34x1G.

The MSP 34x1G has all functions of the MSP 34x0G with the addition of a virtual surround sound feature.

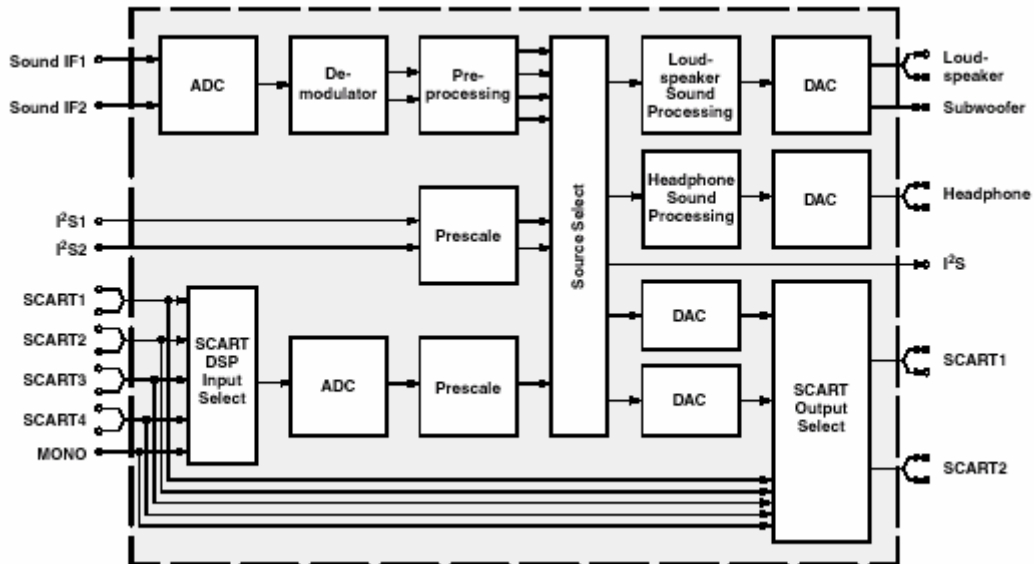
Surround sound can be reproduced to a certain extent with two loudspeakers. The MSP 34x1G includes the Micronas virtualizer algorithm "3D-PANORAMA" which has been approved by the Dolby 1) Laboratories for with the "Virtual Dolby Surround" technology. In addition, the MSP 34x1G includes the "PAN-ORAMA" algorithm.

These TV sound processing ICs include versions for processing the multichannel television sound (MTS) signal conforming to the standard recommended by the Broadcast Television Systems Committee (BTSC). The DBX noise reduction, or alternatively, Micronas Noise Reduction (MNR) is performed alignment free.

Other processed standards are the Japanese FM-FM multiplex standard (EIA-J) and the FM Stereo Radio standard.

Current ICs have to perform adjustment procedures in order to achieve good stereo separation for BTSC and EIA-J. The MSP 34x1G has optimum stereo performance without any adjustments.

The MSP 34x1G has built-in automatic functions: The IC is able to detect the actual sound standard automatically (Automatic Standard Detection). Furthermore, pilot levels and identification signals can be evaluated internally with subsequent switching between mono/stereo/bilingual; no I²C interaction is necessary (Automatic Sound Selection).



Source Select

I²S bus interface consists of five pins:

1. I²S_DA_IN1, I²S_DA_IN2: For input, four channels (two channels per line, 2*16 bits) per sampling cycle (32 kHz) are transmitted.
2. I²S_DA_OUT: For output, two channels (2*16 bits) per sampling cycle (32 kHz) are transmitted.
3. I²S_CL: Gives the timing for the transmission of I²S serial data (1.024 MHz).
4. I²S_WS: The I²S_WS word strobe line defines the left and right sample.

12.15.2. Features

- 3D-PANORAMA virtualizer (approved by Dolby Laboratories) with noise generator
- PANORAMA virtualizer algorithm
- Standard Selection with single I²C transmission
- Automatic Sound Selection (mono/stereo/bilingual),
- Automatic Carrier Mute function
- Interrupt output programmable (indicating status change)
- Loudspeaker / Headphone channel with volume, balance, bass, treble, loudness
- AVC: Automatic Volume Correction
- Subwoofer output with programmable low-pass and complementary high-pass filter
- 5-band graphic equalizer for loudspeaker channel
- Spatial effect for loudspeaker channel, processing of all deemphasis filtering
- Two selectable sound IF (SIF) inputs
- Four Stereo SCART (line) inputs, one Mono input; two Stereo SCART outputs
- Complete SCART in/out switching matrix
- Two I²S inputs; one I²S output
- Automatic Standard Detection of terrestrial TV standards
- Demodulation of the BTSC multiplex signal and the SAP channel
- Alignment free digital DBX noise reduction
- BTSC stereo separation (MSP 3441G also EIA-J) significantly better than specification
- SAP and stereo detection for BTSC system
- Demodulation of the FM-Radio multiplex signal

12.15.3. Pin connections

NC = not connected; leave vacant

LV = if not used, leave vacant

OBL = obligatory; connect as described in circuit diagram

DVSS: if not used, connect to DVSS

AHVSS: connect to AHVSS

Pin No.					Pin Name	Type	Connection (if not used)	Short Description
PLCC 68-pin	PSDIP 64-pin	PSDIP 52-pin	PQFP 80-pin	PLQFP 64-pin				
1	16	14	9	8	ADR_WS	OUT	LV	ADR word strobe
2	-	-	-	-	NC		LV	Not connected
3	15	13	8	7	ADR_DA	OUT	LV	ADR Data Output
4	14	12	7	6	I2S_DA_IN1	IN	LV	I ² S1 data input
5	13	11	6	5	I2S_DA_OUT	OUT	LV	I ² S data output
6	12	10	5	4	I2S_WS	IN/OUT	LV	I ² S word strobe
7	11	9	4	3	I2S_CL	IN/OUT	LV	I ² S clock
8	10	8	3	2	I2C_DA	IN/OUT	OBL	I ² C data
9	9	7	2	1	I2C_CL	IN/OUT	OBL	I ² C clock
10	8	-	1	64	NC		LV	Not connected
11	7	6	80	63	STANDBYQ	IN	OBL	Stand-by (low-active)
12	6	5	79	62	ADR_SEL	IN	OBL	I ² C bus address select
13	5	4	78	61	D_CTR_I/O_0	IN/OUT	LV	D_CTR_I/O_0
14	4	3	77	60	D_CTR_I/O_1	IN/OUT	LV	D_CTR_I/O_1
15	3	-	76	59	NC		LV	Not connected
16	2	-	75	58	NC		LV	Not connected
17	-	-	-	-	NC		LV	Not connected
18	1	2	74	57	AUD_CL_OUT	OUT	LV	Audio clock output (18.432 MHz)
19	64	1	73	56	TP		LV	Test pin
20	63	52	72	55	XTAL_OUT	OUT	OBL	Crystal oscillator
21	62	51	71	54	XTAL_IN	IN	OBL	Crystal oscillator
22	61	50	70	53	TESTEN	IN	OBL	Test pin
23	60	49	69	52	ANA_IN2+	IN	AVSS via 56 pF/LV	IF Input 2 (can be left vacant, only if IF input 1 is also not in use)
24	59	48	68	51	ANA_IN-	IN	AVSS via 56 pF/LV	IF common (can be left vacant, only if IF input 1 is also not in use)
25	58	47	67	50	ANA_IN1+	IN	LV	IF input 1

26	57	46	66	49	AVSUP		OBL	Analog power supply 5V
-	-	-	65	-	AVSUP		OBL	Analog power supply 5V
-	-	-	64	-	NC		LV	Not connected
-	-	-	63	-	NC		LV	Not connected
27	56	45	62	48	AVSS		OBL	Analog ground
-	-	-	61	-	AVSS		OBL	Analog ground
28	55	44	60	47	MONO_IN	IN	LV	Mono input
-	-	-	59	-	NC		LV	Not connected
29	54	43	58	46	VREFTOP		OBL	Reference voltage IF A/D converter
30	53	42	57	45	SC1_IN_R	IN	LV	SCART 1 input, right
31	52	41	56	44	SC1_IN_L	IN	LV	SCART 1 input, left
32	51	-	55	43	ASG1		AHVSS	Analog Shield Ground 1
33	50	40	54	42	SC2_IN_R	IN	LV	SCART 2 input, right
34	49	39	53	41	SC2_IN_L	IN	LV	SCART 2 input, left
35	48	-	52	40	ASG2		AHVSS	Analog Shield Ground 2
36	47	38	51	39	SC3_IN_R	IN	LV	SCART 3 input, right
37	46	37	50	38	SC3_IN_L	IN	LV	SCART 3 input, left
38	45	-	49	37	ASG4		AHVSS	Analog Shield Ground 4
39	44	-	48	36	SC4_IN_R	IN	LV	SCART 4 input, right
40	43	-	47	35	SC4_IN_L	IN	LV	SCART 4 input, left
41	-	-	46	-	NC		LV or AHVSS	Not connected
42	42	36	45	34	AGNDC		OBL	Analog reference voltage
43	41	35	44	33	AHVSS		OBL	Analog ground
-	-	-	43	-	AHVSS		OBL	Analog ground
-	-	-	42	-	NC		LV	Not connected
-	-	-	41	-	NC		LV	Not connected
44	40	34	40	32	CAPL_M		OBL	Volume capacitor MAIN
45	39	33	39	31	AHVSUP		OBL	Analog power supply 8V
46	38	32	38	30	CAPL_A		OBL	Volume capacitor AUX
47	37	31	37	29	SC1_OUT_L	OUT	LV	SCART output 1, left
48	36	30	36	28	SC1_OUT_R	OUT	LV	SCART output 1, right
49	35	29	35	27	VREF1		OBL	Reference ground 1
50	34	28	34	26	SC2_OUT_L	OUT	LV	SCART output 2, left
51	33	27	33	25	SC2_OUT_R	OUT	LV	SCART output 2, right
52	-	-	32	-	NC		LV	Not connected
53	32	-	31	24	NC		LV	Not connected
54	31	26	30	23	DACM_SUB	OUT	LV	Subwoofer output
55	30	-	29	22	NC		LV	Not connected
56	29	25	28	21	DACM_L	OUT	LV	Loudspeaker out, left
57	28	24	27	20	DACM_R	OUT	LV	Loudspeaker out, right
58	27	23	26	19	VREF2		OBL	Reference ground 2
59	26	22	25	18	DACA_L	OUT	LV	Headphone out, left
60	25	21	24	17	DACA_R	OUT	LV	Headphone out, right
-	-	-	23	-	NC		LV	Not connected
-	-	-	22	-	NC		LV	Not connected
61	24	20	21	16	RESETQ	IN	OBL	Power-on-reset
62	23	-	20	15	NC		LV	Not connected
63	22	-	19	14	NC		LV	Not connected
64	21	19	18	13	NC		LV	Not connected
65	20	18	17	12	I2S_DA_IN2	IN	LV	I ² S2-data input
66	19	17	16	11	DVSS		OBL	Digital ground
-	-	-	15	-	DVSS		OBL	Digital ground
-	-	-	14	-	DVSS		OBL	Digital ground
67	18	16	13	10	DVSUP		OBL	Digital power supply 5V
-	-	-	12	-	DVSUP		OBL	Digital power supply 5V
-	-	-	11	-	DVSUP		OBL	Digital power supply 5V
68	17	15	10	9	ADR_CL	OUT	LV	ADR clock

12.16. TPA3002D

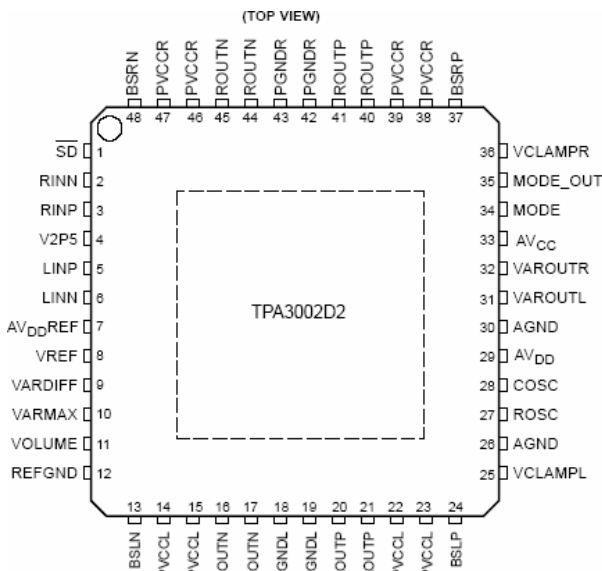
12.16.1. Description

The TPA3002D2 is a 9-W (per channel) efficient, Class-D audio amplifier for driving bridged-tied stereo speakers. The TPA3002D2 can drive stereo speakers as low as 8 Ω . The high efficiency of the TPA3002D2 eliminates the need for external heatsinks when playing music.

FEATURES

- 9-W/Ch Into an 8- Ω Load From 12-V Supply
- Efficient, Class-D Operation Eliminates Heatsinks and Reduces Power Supply Requirements
- 32-Step DC Volume Control From -40 dB to 36 dB
- Line Outputs For External Headphone
- Amplifier With Volume Control
- Regulated 5-V Supply Output for Powering TPA6110A2
- Space-Saving, Thermally-Enhanced PowerPAD Packaging
- Thermal and Short-Circuit Protection

12.16.2. Pin Connection



12.17. TDA1308

12.17.1. General Description

The TDA1308 is an integrated class AB stereo headphone driver contained in an SO8 or a DIP8 plastic package. The device is fabricated in a 1 mm CMOS process and has been primarily developed for portable digital audio applications. It gets its input from two analog audio outputs (DACA_L and DACA_R) of MSP 34x0G. The gain of the output is adjustable by the feedback resistor between the inputs and outputs.

12.17.2. Features

- Wide temperature range
- No switch ON/OFF clicks
- Excellent power supply ripple rejection
- Low power consumption
- Short-circuit resistant
- High performance
- high signal-to-noise ratio

- High slew rate
- Low distortion
- Large output voltage swing.

12.17.3. Pinning

SYMBOL	PIN	DESCRIPTION
OUTA	1	Output A
INA(neg)	2	Inverting input A
INA(pos)	3	Non-inverting input A
V _{SS}	4	Negative supply
INB(pos)	5	Non-inverting input B
INB(neg)	6	Inverting input B
OUTB	7	Output B
V _{DD}	8	Positive supply

12.18. PI5V330

12.18.1. General Description

The PI5V330 is well suited for video applications when switching composite or RGB analog. A picture-in-picture application will be described in this brief. The pixel-rate creates video overlays so two or more pictures can be viewed at the same time. An inexpensive NTSC titler can be implemented by superimposing the output of a character generator on a standard composite video background.

12.19. MST9883

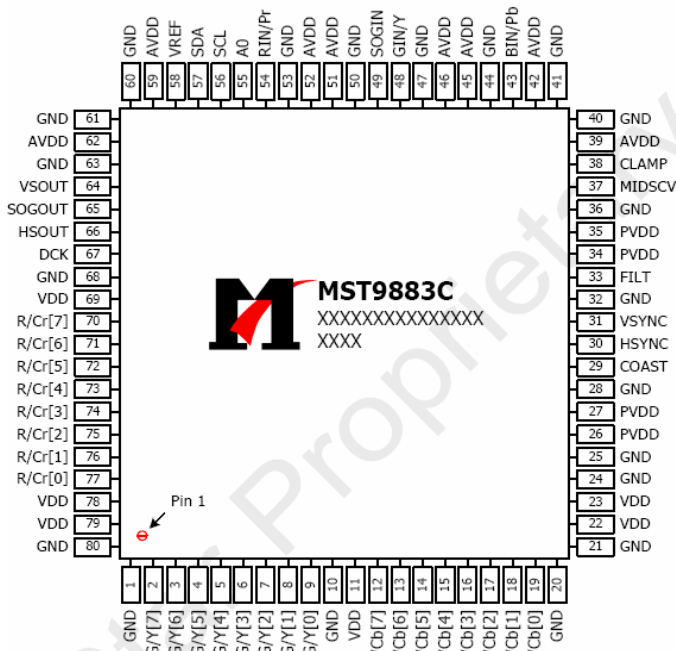
12.19.1. General Description

The MST9883C is a fully integrated analog interface for digitizing high-resolution RGB graphics signals from PC's and workstations. With a sampling rate capability of up to 140 MHz, it can accurately support display resolutions up to 1280x1024 (SXGA) at 75 Hz. The clamped input circuits provide sufficient bandwidth to accurately digitize each pixel.

12.19.2. Features

- Triple ADC with 12 - 140 MHz Sampling Rate
- Integrated line locked PLL generates pixel clock from HSYNC
- Integrated clamp with timing generator
- Integrated Brightness & Contrast controls
- Pin Compatible with AD9883A
- 4:2:2 and 4:4:4 Output Format Mode
- BT656 output format mode*
- Black and mid-level precision clamp and calibration

12.19.3. Pin Descriptions



Pin Name	Pin Type	Function	Pin Number(s)
RED _{IN}	Analog Input	Red analog input	54
GRN _{IN}	Analog Input	Green analog input	48
BLU _{IN}	Analog Input	Blue analog input	43
SOG _{IN}	Analog Input	Sync on Green analog input	49
CLAMP	Digital CMOS Input	External Clamp Input	38
HSYNC	Digital CMOS Input	Horizontal SYNC Input	30
VSYNC	Digital CMOS Input	Vertical SYNC Input	31
COAST	Digital CMOS Input	Hold PLL Frequency, do not track HSYNC	29
SCL	Digital CMOS Input	Serial Interface clock	56
SDA	Digital CMOS Input/Output	Serial Interface data pin	57
A ₀	Digital CMOS Input	Serial interface address pin	55
R [7:0]	Digital CMOS 3-state Output	Red output data	70-77
G [7:0]	Digital CMOS 3-state Output	Green output data	2-9
B [7:0]	Digital CMOS 3-state Output	Blue output data	12-19
DCK	Digital CMOS 3-state Output	Output data clock	67
HSOUT	Digital CMOS 3-state Output	HSYNC output	66
VSOUT	Digital CMOS 3-state Output	VSYNC output	64
SOG _{OUT}	Digital CMOS 3-state Output	SYNC on Green Slicer Output	65
FILT		No Connection	33
VREF	Reference	Internal Reference Bypass	58
MIDSCV	Reference	Internal Mid-Scale Voltage Bypass	37
AV _{DD}	3.3v Power	Analog Power	39,42,45,46,51,52,59,62
PV _{DD}	3.3v Power	PLL Power	26,27,34,35
V _{DD}	3.3v Power	Digital Output Power	11,22, 23, 69,78,79
GND	System Ground	System Ground	1,10,20,21,24,25,28,32,36, 40,41,44,47,50,53,60,61,63, 68,80

12.20. SAA7118E

12.20.1. General Description

The SAA7118E is a video capture device for applications at the image port of VGA controllers. Philips X-VIP is a new multistandard comb filter video decoder chip with additional component processing, providing high quality, optionally scaled, video.

The SAA7118E is a combination of a four-channel analog preprocessing circuit including source selection, anti-aliasing filter and ADC, an automatic clamp and gain control, a Clock Generation Circuit (CGC), a digital multistandard decoder containing two-dimensional chrominance/luminance separation by an adaptive comb filter and a high performance scaler, including variable horizontal and vertical up and downscaling and a brightness, contrast and saturation control circuit.

It is a highly integrated circuit for desktop video and similar applications. The decoder is based on the principle of line-locked clock decoding and is able to decode the colour of PAL, SECAM and NTSC signals into ITU 601 compatible colour component values. The SAA7118E accepts CVBS or S-video (Y/C) as analog inputs from TV or VCR sources, including weak and distorted signals as well as baseband component signals Y-P_B -P_R or RGB. An expansion port (X-port) for digital video (bidirectional half duplex, D1 compatible) is also supported to connect to MPEG or video phone codec. At the so called image port (I-port) the SAA7118E supports 8 or 16-bit wide output data with auxiliary reference data for interfacing to VGA controllers.

The target application for the SAA7118E is to capture and scale video images, to be provided as digital video stream through the image port of a VGA controller, for capture to system memory, or just to provide digital baseband video to any picture improvement processing.

12.20.2. Features

Video acquisition/clock

- Up to sixteen analog CVBS, split as desired (all of the CVBS inputs optionally can be used to convert e.g. Vestigial Side Band (VSB) signals)
- Up to eight analog Y + C inputs, split as desired
- Up to four analog component inputs, with embedded or separate sync, split as desired
- Four on-chip anti-aliasing filters in front of the Analog-to-Digital Converters (ADCs)
- Automatic Clamp Control (ACC) for CVBS, Y and C (or VSB) and component signals
- Switchable white peak control
- Four 9-bit low noise CMOS ADCs running at twice the oversampling rate (27 MHz)
- Fully programmable static gain or Automatic Gain Control (AGC), matching to the particular signal properties
- On-chip line-locked clock generation in accordance with "ITU 601"
- Requires only one crystal (32.11 or 24.576 MHz) for all standards
- Horizontal and vertical sync detection.

Video decoder

- Digital PLL for synchronization and clock generation from all standards and non-standard video sources e.g. consumer grade VTR
- Automatic detection of any supported colour standard
- Luminance and chrominance signal processing for PAL B, G, D, H, I and N, combination PAL N, PAL M, NTSC M, NTSC-Japan, NTSC 4.43 and SECAM
- Adaptive 2/4-line comb filter for two dimensional chrominance/luminance separation, also with VTR signals
 - Increased luminance and chrominance bandwidth for all PAL and NTSC standards
 - Reduced cross colour and cross luminance artefacts
- PAL delay line for correcting PAL phase errors
- Brightness Contrast Saturation (BCS) adjustment, separately for composite and baseband signals
- User programmable sharpness control
- Detection of copy-protected signals according to the macrovision standard, indicating level of protection
- Independent gain and offset adjustment for raw data path.

Component video processing

- RGB component inputs
- Y-P_B -P_R component inputs

- Fast blanking between CVBS and synchronous component inputs
- Digital RGB to Y-C_B-C_R matrix.

Video scaler

- Horizontal and vertical downscaling and upscaling to randomly sized windows
- Horizontal and vertical scaling range: variable zoom to 1/64 (icon) (note: H and V zoom are restricted by the transfer data rates)
- Anti-alias and accumulating filter for horizontal scaling
- Vertical scaling with linear phase interpolation and accumulating filter for anti-aliasing (6-bit phase accuracy)
- Horizontal phase correct up and downscaling for improved signal quality of scaled data, especially for compression and video phone applications, with 6-bit phase accuracy (1.2 ns step width)
- Two independent programming sets for scaler part, to define two 'ranges' per field or sequences over frames
- Fieldwise switching between decoder part and expansion port (X-port) input
- Brightness, contrast and saturation controls for scaled outputs.

Vertical Blanking Interval (VBI) data decoder and slicer

- Versatile VBI-data decoder, slicer, clock regeneration and byte synchronization e.g. for World Standard Teletext (WST), North-American Broadcast Text System (NABTS), close caption, Wide Screen Signalling (WSS) etc.

Audio clock generation

- Generation of a field-locked audio master clock to support a constant number of audio clocks per video field
- Generation of an audio serial and left/right (channel)

Digital I/O interfaces

- Real-time signal port (R port), inclusive continuous line-locked reference clock and real-time status information supporting RTC level 3.1 (refer to document "RTC Functional Specification" for details)
- Bidirectional expansion port (X-port) with half duplex functionality (D1), 8-bit Y-C_B-C_R
 - Output from decoder part, real-time and unscaled
 - Input to scaler part, e.g. video from MPEG decoder (extension to 16-bit possible)
- Video image port (I-port) configurable for 8-bit data (extension to 16-bit possible) in master mode (own clock), or slave mode (external clock), with auxiliary timing and handshake signals
- Discontinuous data streams supported
- 32-word ´ 4-byte FIFO register for video output data
- 28-word ´ 4-byte FIFO register for decoded VBI-data output
- Scaled 4 :2 :2, 4 :1 :1, 4 :2 :0, 4 :1 :0 Y-C_B-C_R output
- Scaled 8-bit luminance only and raw CVBS data output
- Sliced, decoded VBI-data output.

Miscellaneous

- Power-on control
- 5 V tolerant digital inputs and I/O ports
- Software controlled power saving standby modes supported
- Programming via serial I 2 C-bus, full read back ability by an external controller, bit rate up to 400 kbits/s
- Boundary scan test circuit complies with the "IEEE Std. 1149.b1 - 1994"
- BGA156 package.

12.20.3. Pinning

SYMBOL	PIN	TYPE	DESCRIPTION
XTOUT	A2	O	crystal oscillator output signal; auxiliary signal
XTALO	A3	O	24.576 MHz (32.11 MHz) crystal oscillator output; not connected if TTL clock input of XTALI is used
V _{SS(xtal)}	A4	P	ground for crystal oscillator
TDO	A5	O	test data output for boundary scan test; note 2
XRDY	A6	O	task flag or ready signal from scaler, controlled by XRQT
XCLK	A7	I/O	clock I/O expansion port

XPD0	A8	I/O	LSB of expansion port data
XPD2	A9	I/O	MSB - 5 of expansion port data
XPD4	A10	I/O	MSB - 3 of expansion port data
XPD6	A11	I/O	MSB - 1 of expansion port data
TEST1	A12	I/pu	do not connect, reserved for future extensions and for testing: scan input
TEST2	A13	I/pu	do not connect, reserved for future extensions and for testing: scan input
AI41	B1	I	analog input 41
TEST3	B2	O	do not connect, reserved for future extensions and for testing
V _{DD(xtal)}	B3	P	supply voltage for crystal oscillator
XTALI	B4	I	input terminal for 24.576 MHz (32.11 MHz) crystal oscillator or connection of external oscillator with TTL compatible square wave clock signal
TDI	B5	I/pu	test data input for boundary scan test; note 2
TCK	B6	I/pu	test clock for boundary scan test; note 2
XDQ	B7	I/O	data qualifier for expansion port
XPD1	B8	I/O	MSB - 6 of expansion port data
XPD3	B9	I/O	MSB - 4 of expansion port data
XPD5	B10	I/O	MSB - 2 of expansion port data
XTRI	B11	I	X-port output control signal, affects all X-port pins (XPD7 to XPD0, XRH, XRV, XDQ and XCLK), enable and active polarity is under software control (bits XPE in subaddress 83H)
TEST4	B12	O	do not connect, reserved for future extensions and for testing: scan output
TEST5	B13	NC	do not connect, reserved for future extensions and for testing
TEST6	B14	NC	do not connect, reserved for future extensions and for testing
VSSA4	C1	P	ground for analog inputs AI4x
AGND	C2	P	analog ground
TEST7	C3	NC	do not connect, reserved for future extensions and for testing
TEST8	C4	NC	do not connect, reserved for future extensions and for testing
V _{DD1}	C5	P	digital supply voltage 1 (peripheral cells)
TRST	C6	I/pu	test reset input (active LOW), for boundary scan test (with internal pull-up); notes 2, 3 and 4
XRH	C7	I/O	horizontal reference I/O expansion port
V _{DD2}	C8	P	digital supply voltage 2 (core)
V _{DD3}	C9	P	digital supply voltage 3 (peripheral cells)
V _{DD4}	C10	P	digital supply voltage 4 (core)
XPD7	C11	I/O	MSB of expansion port data
TEST9	C12	NC	do not connect, reserved for future extensions and for testing
TEST10	C13	NC	do not connect, reserved for future extensions and for testing
TEST11	C14	I/pu	do not connect, reserved for future extensions and for testing: scan input
AI43	D1	I	analog input 43
AI42	D2	I	analog input 42
AI4D	D3	I	differential input for ADC channel 4 (pins AI41 to AI44)
V _{DDA4}	D4	P	analog supply voltage for analog inputs AI4x (3.3 V)
V _{SS1}	D5	P	digital ground 1 (peripheral cells)
TMS	D6	I/pu	test mode select input for boundary scan test or scan test; note 2
V _{SS2}	D7	P	digital ground 2 (core; substrate connection)
XRV	D8	I/O	vertical reference I/O expansion port
V _{SS3}	D9	P	digital ground 3 (peripheral cells)
V _{SS4}	D10	P	digital ground 4 (core)
V _{SS5}	D11	P	digital ground 5 (peripheral cells)
V _{DD5}	D12	P	digital supply voltage 5 (peripheral cells)
TEST12	D13	I/pu	do not connect, reserved for future extensions and for testing: scan input
HPD0	D14	I/O	LSB of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
AI44	E1	I	analog input 44
V _{DDA4A}	E2	P	analog supply voltage for analog inputs AI4x (3.3 V)
AI31	E3	I	analog input 31

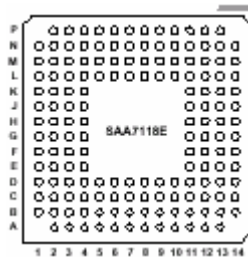
V _{SSA3}	E4	P	ground for analog inputs AI3x
HPD1	E11	I/O	MSB - 6 of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
HPD3	E12	I/O	MSB - 4 of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
HPD2	E13	I/O	MSB - 5 of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
HPD4	E14	I/O	MSB - 3 of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
AI3D	F1	I/O	differential input for ADC channel 3 (pins AI31 to AI34)
AI32	F2	I	analog input 32
AI33	F3	I	analog input 33
V _{DDA3}	F4	P	analog supply voltage for analog inputs AI3x (3.3 V)
V _{SSD6}	F11	P	digital ground 6 (core)
V _{DD6}	F12	P	digital supply voltage 6 (core)
HPD5	F13	I/O	MSB - 2 of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
HPD6	F14	I/O	MSB - 1 of host port data I/O, extended C _B -C _R input for expansion port, extended C _B -C _R output for image port
AI34	G1	I	analog input 34
V _{DDA3A}	G2	P	analog supply voltage for analog inputs AI3x (3.3 V)
AI22	G3	I	analog input 22
AI21	G4	I	analog input 21
V _{SSD7}	G11	P	digital ground 7 (peripheral cells)
IPD1	G12	O	MSB - 6 of image port data output
HPD7	G13	I/O	MSB of host port data I/O, extended C _B -C _R R input for expansion port, extended C _B -C _R output for image port
IPD0	G14	O	LSB of image port data output
AI2D	H1	I	differential input for ADC channel 2 (pins AI24 to AI21)
AI23	H2	I	analog input 23
V _{SSA2}	H3	P	ground for analog inputs AI2x
V _{DDA2}	H4	P	analog supply voltage for analog inputs AI2x
IPD2	H11	O	MSB - 5 of image port data output
V _{DD7}	H12	P	digital supply voltage 7 (peripheral cells)
IPD4	H13	O	MSB - 3 of image port data output
IPD3	H14	O	MSB - 4 of image port data output
V _{DDA2A}	J1	P	analog supply voltage for analog inputs AI2x
AI11	J2	I	analog input 11
AI24	J3	I	analog input 24
V _{SSA1}	J4	P	ground for analog inputs AI1x
V _{SSD8}	J11	P	digital ground 8 (core)
V _{DD8}	J12	P	digital supply voltage 8 (core)
IPD6	J13	O	MSB - 1 of image port data output
IPD5	J14	O	MSB - 2 of image port data output
AI12	K1	I	analog input 12
AI13	K2	I	analog input 13
AI1D	K3	I	differential input for ADC channel 1 (pins AI14 to AI11)
V _{DDA1}	K4	P	analog supply voltage for analog inputs AI1x (3.3 V)
IPD7	K11	O	MSB of image port data output
IGPH	K12	O	multi purpose horizontal reference output signal; image port (controlled by subaddresses 84H and 85H)
IGP1	K13	O	general purpose output signal 1; image port (controlled by subaddresses 84H and 85H)
IGPV	K14	O	multi purpose vertical reference output signal; image port (controlled by subaddresses 84H and 85H)
V _{DDA1A}	L1	P	analog supply voltage for analog inputs AI1x (3.3 V)
AGNDA	L2	P	analog signal ground
AI14	L3	I	analog input 14
V _{SSD9}	L4	P	digital ground 9 (peripheral cells)
V _{SSD10}	L5	P	digital ground 10 (core)
ADP6	L6	O	MSB - 2 of direct analog-to-digital converted output data (VSB)
ADP3	L7	O	MSB - 5 of direct analog-to-digital converted output data (VSB)

V _{SSD11}	L8	P	digital ground 11 (peripheral cells)
V _{SSD12}	L9	P	digital ground 12 (core)
RTCO	L10	O/st/pd	real-time control output; contains information about actual system clock frequency, field rate, odd/even sequence, decoder status, subcarrier frequency and phase and PAL sequence; the RTCO pin is enabled via I ² C-bus bit RTCE; see notes 5, 6
V _{SSD13}	L11	P	digital ground 13 (peripheral cells)
ITRI	L12	I/(O)	image port output control signal, affects all input port pins inclusive ICLK, enable and active polarity is under software control (bits IPE in subaddress 87H); output path used for testing: scan output
IDQ	L13	O	output data qualifier for image port (optional: gated clock output)
IGP0	L14	O	general purpose output signal 0; image port (controlled by subaddresses 84H and 85H)
AOUT	M1	O	analog test output (do not connect)
V _{SSA0}	M2	P	ground for internal Clock Generation Circuit (CGC)
V _{DDA0}	M3	P	analog supply voltage (3.3 V) for internal clock generation circuit
V _{DDD9}	M4	P	digital supply voltage 9 (peripheral cells)
V _{DDD10}	M5	P	digital supply voltage 10 (core)
ADP7	M6	O	MSB – 1 of direct analog-to-digital converted output data (VSB)
ADP2	M7	O	MSB – 6 of direct analog-to-digital converted output data (VSB)
V _{DDD11}	M8	P	digital supply voltage 11 (peripheral cells)
V _{DDD12}	M9	P	digital supply voltage 12 (core)
RTS0	M10	O	real-time status or sync information, controlled by subaddresses 11H and 12H
V _{DDD13}	M11	P	digital supply voltage 13 (peripheral cells)
AMXCLK	M12	I	audio master external clock input
FSW	M13	I/pd	fast switch (blanking) with internal pull-down inserts component inputs into CVBS signal
ICLK	M14	I/O	clock output signal for image port, or optional asynchronous back-end clock input
TEST13	N1	NC	do not connect, reserved for future extensions and for testing
TEST14	N2	I/pu	do not connect, reserved for future extensions and for testing
TEST15	N3	I/pd	do not connect, reserved for future extensions and for testing
CE	N4	I/pu	chip enable or reset input (with internal pull-up)
LLC2	N5	O	line-locked 1 $\times$ 2 clock output (13.5 MHz nominal)
CLKEXT	N6	I	external clock input intended for analog-to-digital conversion of VSB signals (36 MHz)
ADP5	N7	O	MSB - 3 of direct analog-to-digital converted output data (VSB)
ADP0	N8	O	LSB of direct analog-to-digital converted output data (VSB)
SCL	N9	I	serial clock input (I ² C-bus)
RTS1	N10	O	real-time status or sync information, controlled by subaddresses 11H and 12H
ASCLK	N11	O	audio serial clock output
ITRDY	N12	I	target ready input for image port data
TEST16	N13	NC	do not connect, reserved for future extensions and for testing
TEST17	N14	NC	do not connect, reserved for future extensions and for testing
TEST18	P2	I/O	do not connect, reserved for future extensions and for testing
EXMCLR	P3	I/pd	external mode clear (with internal pull-down)
LLC	P4	O	line-locked system clock output (27 MHz nominal)
RES	P5	O	reset output (active LOW)
ADP8	P6	O	MSB of direct analog-to-digital converted output data (VSB)
ADP4	P7	O	MSB - 4 of direct analog-to-digital converted output data (VSB)
ADP1	P8	O	MSB - 7 of direct analog-to-digital converted output data (VSB)
INT_A	P9	O/od	I ² C-bus interrupt flag (LOW if any enabled status bit has changed)

SDA	P10	I/O/od	serial data input/output (I 2 C-bus)
AMCLK	P11	O	audio master clock output, up to 50% of crystal clock
ALRCLK	P12	O/st/pd	audio left/right clock output; can be strapped to supply via a 3.3 kW resistor to indicate that the default 24.576 MHz crystal (ALRCLK = 0; internal pull-down) has been replaced by a 32.110 MHz crystal (ALRCLK = 1); see notes 5 and 7
TEST19	P13	I/pu	do not connect, reserved for future extensions and for testing: scan input

Notes

1. I = input, O = output, P = power, NC = not connected, st = strapping, pu = pull-up, pd = pull-down, od = open-drain.
2. In accordance with the "IEEE1149.1" standard the pads TDI, TMS, TCK and TRST are input pads with an internal pull-up transistor and TDO is a 3-state output pad.
3. For board design without boundary scan implementation connect the TRST pin to ground.
4. This pin provides easy initialization of the Boundary Scan Test (BST) circuit. TRST can be used to force the Test Access Port (TAP) controller to the TEST_LOGIC_RESET state (normal operation) at once.
5. Pin strapping is done by connecting the pin to the supply via a 3.3 kΩ resistor. During the power-up reset sequence the corresponding pins are switched to input mode to read the strapping level. For the default setting no strapping resistor is necessary (internal pull-down).
6. Pin RTCO operates as I 2 C-bus slave address pin; RTCO = 0 slave address 42H/43H (default); RTCO = 1 slave address 40H/41H.
7. Pin ALRCLK: 0 = 24.576 MHz crystal (default; Philips order number 4322 143 05291); 1 = 32.110 MHz crystal



12.21. TPS72501

12.21.1. General Description

The TPS725xx family of 1-A low-dropout (LDO) linear regulators has fixed voltage options available that are commonly used to power the latest DSPs, FPGAs, and microcontrollers. An adjustable option ranging from 1.22 V to 5.5 V is also available. The integrated supervisory circuitry provides an active low RESET signal when the output falls out of regulation. The no capacitor/any capacitor feature allows the customer to tailor output transient performance as needed. Therefore, compared to other regulators capable of providing the same output current, this family of regulators can provide a stand alone power supply solution or a post regulator for a switch mode power supply.

These regulators are ideal for higher current applications. The family operates over a wide range of input voltages (1.8 V to 6 V) and has very low dropout (170 mV at 1-A).

Ground current is typically 210 µA at full load and drops to less than 80 µA at no load. Standby current is less than 1 µA.

Each regulator option is available in either a SOT223–5, D (TPS72501 only), or DDPACK package. With a low input voltage and properly heatsinked package, the regulator dissipates more power and achieves higher efficiencies than similar regulators requiring 2.5 V or more minimum input voltage and higher quiescent currents. These features make it a viable power supply solution for portable, battery powered equipment.

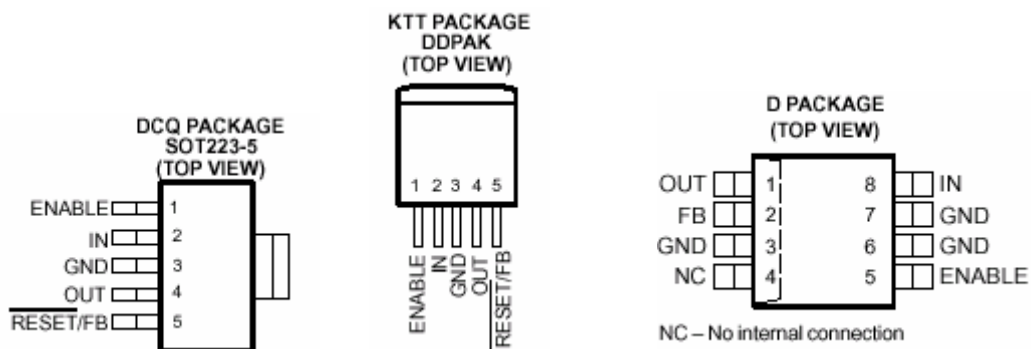
Although an output capacitor is not required for stability, transient response and output noise are improved with a 10-µF output capacitor.

Unlike some regulators that have a minimum current requirement, the TPS725 family is stable with no output load current. The low noise capability of this family, coupled with its high current operation and

ease of power dissipation, make it ideal for telecom boards, modem banks, and other noise sensitive applications.

12.21.2. Features

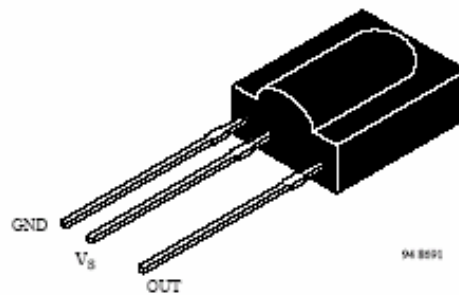
- 1-A Output Current
- Available in 1.5-V, 1.6-V, 1.8-V, 2.5-V Fixed-Output and Adjustable Versions (1.2-V to 5.5-V)
- Input Voltage Down to 1.8 V
- Low 170-mV Dropout Voltage at 1 A (TPS72525)
- Stable With Any Type/Value Output Capacitor
- Integrated Supervisor (SVS) With 50-ms RESET Delay Time
- Low 210- μ A Ground Current at Full Load (TPS72525)
- Less than 1- μ A Standby Current
- $\pm 2\%$ Output Voltage Tolerance Over Line, Load, and Temperature (-40°C to 125°C)
- Integrated UVLO
- Thermal and Overcurrent Protection
- 5-Lead SOT223–5 or DPAK and 8–Pin SOP (TPS72501 only) Surface Mount Package



12.22. TSOP1136

Description

The TSOP11... series are miniaturized receivers for infrared remote control systems. PIN diode and preamplifier are assembled on lead frame, the epoxy package is designed as IR filter. The demodulated output signal can directly be decoded by a microprocessor. The main benefit is the operation with short burst transmission codes (e.g. RECS 80) and high data rates.



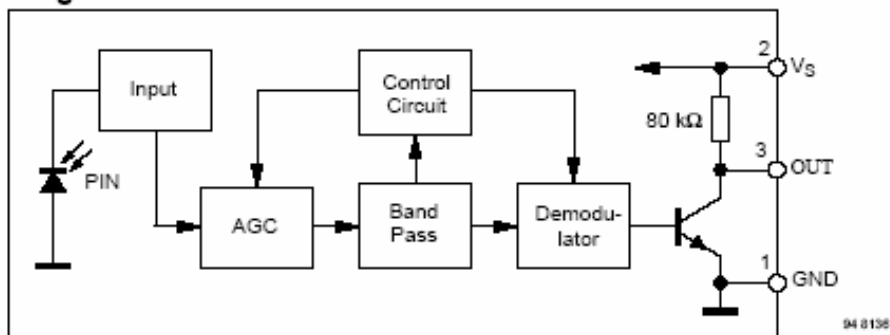
Features

- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Improved shielding against electrical field disturbance
- TTL and CMOS compatibility
- Output active low
- Low power consumption
- High immunity against ambient light

Special Features

- Enhanced data rate of 3500 bit/s
- Operation with short bursts possible (≥6 cycles/burst)

Block Diagram



12.23. PCF8591

12.23.1. General Description

The PCF8591 is a single-chip, single-supply low power 8-bit CMOS data acquisition device with four analog inputs, one analog output and a serial I²C-bus interface.

Three address pins A0, A1 and A2 are used for programming the hardware address, allowing the use of up to eight devices connected to the I²C-bus without additional hardware. Address, control and data to and from the device are transferred serially via the two-line bidirectional I²C-bus.

The functions of the device include analog input multiplexing, on-chip track and hold function, 8-bit analog-to-digital conversion and an 8-bit digital-to-analog conversion. The maximum conversion rate is given by the maximum speed of the I²C-bus.

12.23.2. Features

- Single power supply
- Operating supply voltage 2.5 V to 6 V
- Low standby current
- Serial input/output via I²C-bus
- Address by 3 hardware address pins
- Sampling rate given by I²C-bus speed
- 4 analog inputs programmable as single-ended or differential inputs
- Auto-incremented channel selection
- Analog voltage range from vss to vdd

- On-chip track and hold circuit
- 8-bit successive approximation A/D conversion
- Multiplying DAC with one analog output.

12.23.3. Pinning

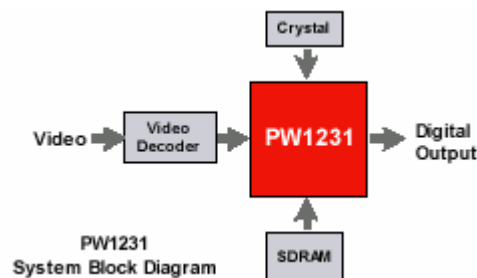
SYMBOL	PIN	DESCRIPTION
AIN0	1	analog inputs (A/D converter)
AIN1	2	
AIN2	3	
AIN3	4	
A0	5	hardware address
A1	6	
A2	7	
V _{SS}	8	negative supply voltage
SDA	9	I ² C-bus data input/output
SCL	10	I ² C-bus clock input
OSC	11	oscillator input/output
EXT	12	external/internal switch for oscillator input
AGND	13	analog ground
V _{REF}	14	voltage reference input
AOUT	15	analog output (D/A converter)
V _{DD}	16	positive supply voltage

12.24. PW1231

12.24.1. General Description

The PW1231 is a high-quality, digital video signal processor that incorporates Pixelworks' patented deinterlacing, scaling, and video enhancement algorithms. The PW1231 accepts industry-standard video formats and resolutions, and converts the input into any desired output format. The video algorithms are highly efficient, providing excellent quality video.

The PW1231 Video SignalProcessor combines many functions into a single device, including memory controller, auto-configuration, and others. This high level of integration enables simple, flexible, cost-effective solutions featuring fewer required components.



12.24.2. Features

- Built-In Memory Controller
- Motion-Adaptive Deinterlace Processor
- Intelligent Edge Deinterlacing
- Digital Color/Luminance Transient Improvement (DCTI/DLTI)
- Interlaced Video Input Options, including NTSC and PAL
- Independent horizontal and vertical scaling
- Copy Protection
- Two-Wire Serial Interface

12.24.3. Applications

- For use with Digital Displays
- Flat-Panel (LCD, DLP) TVs

- Rear Projection TVs
- Plasma Displays
- LCD Multimedia Monitors
- Multimedia Projectors

12.25. PW181

12.25.1. General Description

The PW181 ImageProcessor is a highly integrated “system-on-a-chip” that interfaces computer graphics and video inputs in virtually any format to a fixed-frequency flat panel display.

Computer and video images from NTSC/PAL to WUXGA at virtually any refresh rate can be resized to fit on a fixed-frequency target display device with any resolution up to WUXGA. Video data from 4:3 aspect ratio NTSC or PAL and 16:9 aspect ratio HDTV or SDTV is supported. Multi-region, nonlinear scaling allows these inputs to be resized optimally for the native resolution of the display.

Advanced scaling techniques are supported, such as format conversion using multiple programmable regions. Three independent image scalers coupled with frame locking circuitry and dual programmable color lookup tables create sharp images in multiple windows, without user intervention.

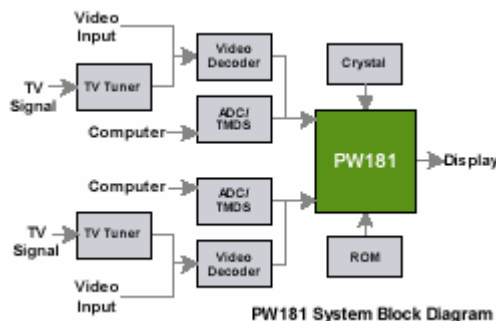
Embedded SDRAM frame buffers and memory controllers perform frame rate conversion and enhanced video processing completely on-chip. A separate memory is dedicated to storage of on-screen display images and CPU general purpose use.

Advanced video processing techniques are supported using the internal frame buffer, including motion adaptive, temporal deinterlacing with film mode detection. When used in combination with the new third-generation scaler, this advanced video processing technology delivers the highest quality video for advanced displays.

Both input ports support integrated DVI 1.0 content protection using standard DVI receivers.

A new advanced OSD Generator with more colors and larger sizes supports more demanding OSD applications, such as on-screen programming guides. When coupled with the new, faster, integrated microprocessor, this OSD Generator supports advanced OSD animation techniques.

Programmable features include the user interface, custom start-up screen, all automatic imaging features, and special screen effects.



12.25.2. Features

- Third-generation, two-dimensional filtering techniques
- Third-generation, advanced scaling techniques
- Second-generation Automatic Image Optimization
- Frame rate conversion
- Video processing
- On-Screen Display (OSD)
- On-chip microprocessor
- JTAG debugger and boundary scan
- Picture-in-picture (PIP)
- Multi-region, non-linear scaling
- Hardware 2-wire serial bus support

12.25.3. Applications

- Multimedia Displays
- Plasma Displays

- Digital Television

12.26. SiI1169

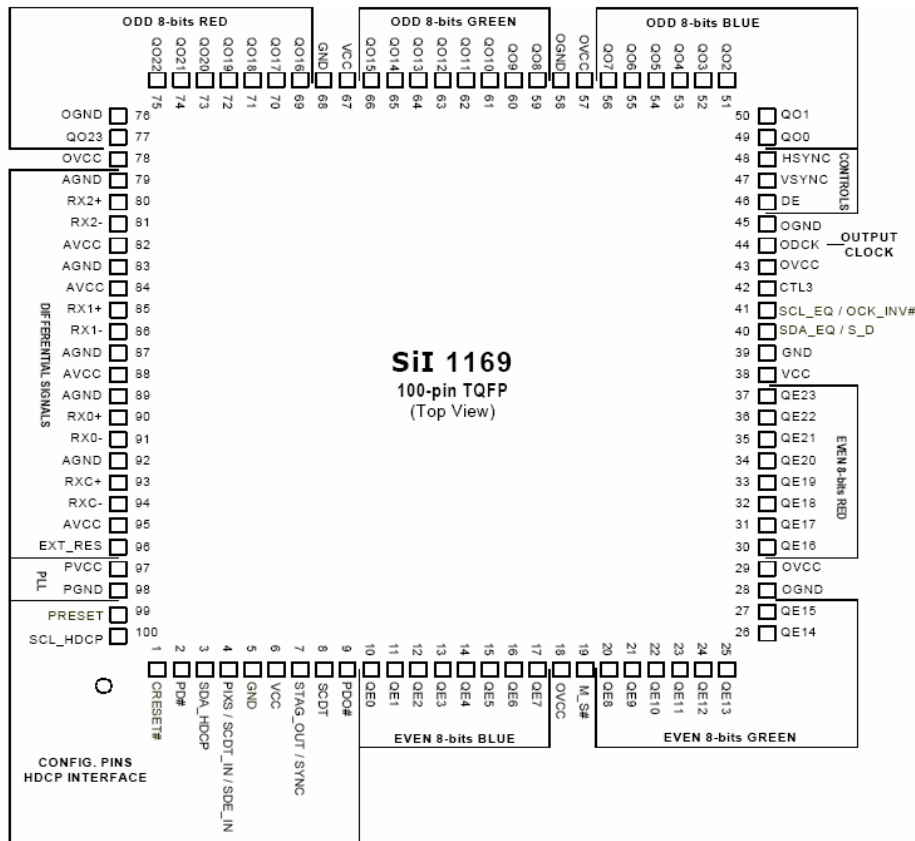
12.26.1. General Description

The SiI 1169 receiver uses PanelLink Digital technology to support high-resolution digital displays for PC and HDTV applications. The SiI 1169 device features High-bandwidth Digital Content Protection (HDCP) for secure delivery of high-definition video, and comes with integrated, pre-programmed HDCP keys to simplify manufacturing and provide the highest level of security.

12.26.2. Features

- Integrated 25-165MHz PanelLink DVI 1.0 compliant core supports VGA to UXGA resolutions
- Supports HDTV resolutions (720p/1080i/1080p)
- Integrated HDCP decryption engine for viewing protected content
- Pre-programmed HDCP keys provide highest level of key security, simplify manufacturing
- Backwards compatible with SiI 161B, SiI 169, SiI 1161, SiI 163B, and TFP401
- Flexible low power modes with automatic power down when input clock is inactive
- Cost-reducing 5V-tolerant DDC I2C interface
- Universal Pb-free package

12.26.3. Pin Connections



12.27. SDRAM 4M x 16 (MT48LC4M16A2TG-75)

12.27.1. General Description

The Micron® 64Mb SDRAM is a high-speed CMOS, dynamic random-access memory containing 67,108,864 bits. It is internally configured as a quad-bank DRAM with a synchronous interface (all signals are registered on the positive edge of the clock signal, CLK). Each of the x4's 16,777,216-bit banks is organized as 4,096 rows by 1,024 columns by 4 bits. Each of the x8's 16,777,216-bit banks is organized as 4,096 rows by 512 columns by 8 bits. Each of the x16's 16,777,216-bit banks is organized as 4,096 rows by 256 columns by 16 bits.

Read and write accesses to the SDRAM are burst oriented; accesses start at a selected location and continue for a programmed number of locations in a programmed sequence. Accesses begin with the registration of an ACTIVE command, which is then followed by a READ or WRITE command. The address bits registered coincident with the ACTIVE command are used to select the bank and row to be accessed (BA0, BA1 select the bank; A0-A11 select the row). The address bits registered coincident with the READ or WRITE command are used to select the starting column location for the burst access. The SDRAM provides for programmable READ or WRITE burst lengths of 1, 2, 4, or 8 locations, or the full page, with a burst terminate option. An auto precharge function may be enabled to provide a self-timed row precharge that is initiated at the end of the burst sequence.

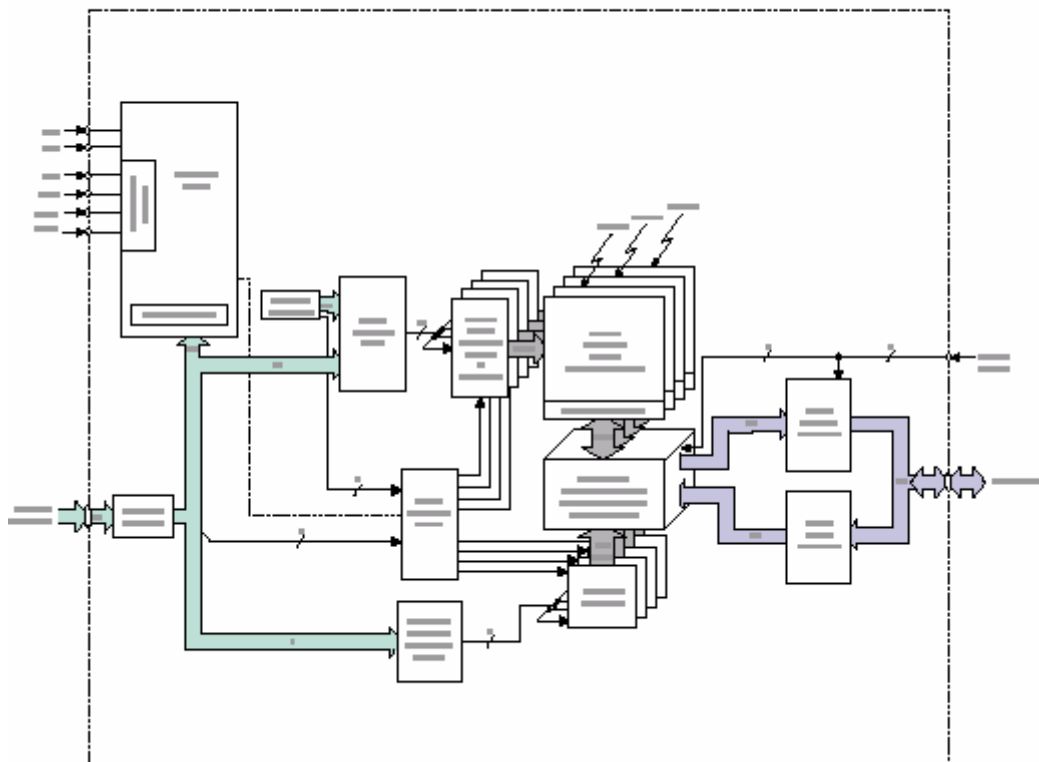
The 64Mb SDRAM uses an internal pipelined architecture to achieve high-speed operation. This architecture is compatible with the $2n$ rule of prefetch architectures, but it also allows the column address to be changed on every clock cycle to achieve a high-speed, fully random access. Precharging one bank while accessing one of the other three banks will hide the precharge cycles and provide seamless, high-speed, random-access operation.

The 64Mb SDRAM is designed to operate in 3.3V memory systems. An auto refresh mode is provided, along with a power-saving, power-down mode. All inputs and outputs are LVTTL-compatible.

SDRAMs offer substantial advances in DRAM operating performance, including the ability to synchronously burst data at a high data rate with automatic column-address generation, the ability to interleave between internal banks in order to hide precharge time and the capability to randomly change column addresses on each clock cycle during a burst access.

FUNCTIONAL BLOCK DIAGRAM

4 Meg x 16 SDRAM



12.27.2. Features

- PC66-, PC100-, and PC133-compliant
- Fully synchronous; all signals registered on positive edge of system clock
- Internal pipelined operation; column address can be changed every clock cycle
- Internal banks for hiding row access/precharge
- Programmable burst lengths: 1, 2, 4, 8, or full page
- Auto Precharge, includes CONCURRENT AUTO PRECHARGE, and Auto Refresh Modes
- Self Refresh Modes: standard and low power
- 64ms, 4,096-cycle refresh
- LVTTTL-compatible inputs and outputs
- Single +3.3V $\pm 0.3V$ power supply

12.27.3. Pin Descriptions

PIN NUMBERS	SYMBOL	TYPE	DESCRIPTION
38	CLK	Input	Clock: CLK is driven by the system clock. All SDRAM input signals are sampled on the positive edge of CLK. CLK also increments the internal burst counter and controls the output registers.
37	CKE	Input	Clock Enable: CKE activates (HIGH) and deactivates (LOW) the CLK signal. Deactivating the clock provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), ACTIVE POWER-DOWN (row active in any bank) or CLOCK SUSPEND operation (burst/access in progress). CKE is synchronous except after the device enters power-down and self refresh modes, where CKE becomes asynchronous until after exiting the same mode. The input buffers, including CLK, are disabled during power-down and self refresh modes, providing low standby power. CKE may be tied HIGH.
19	CS#	Input	Chip Select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple banks. CS# is considered part of the command code.
16, 17, 18	WE#, CAS#, RAS#	Input	Command Inputs: WE#, CAS#, and RAS# (along with CS#) define the command being entered.
39	x4, x8: DQM	Input	Input/Output Mask: DQM is an input mask signal for write accesses and an output enable signal for read accesses. Input data is masked when DQM is sampled HIGH during a WRITE cycle. The output buffers are placed in a High-Z state (two-clock latency) when DQM is sampled HIGH during a READ cycle. On the x4 and x8, DQML (Pin 15) is a NC and DQMH is DQM. On the x16, DQML corresponds to DQ0-DQ7 and DQMH corresponds to DQ8-DQ15. DQML and DQMH are considered same state when referenced as DQM.
15, 39	x16: DQML, DQMH		
20, 21	BA0, BA1	Input	Bank Address Inputs: BA0 and BA1 define to which bank the ACTIVE, READ, WRITE or PRECHARGE command is being applied.
23-26, 29-34, 22, 35	A0-A11	Input	Address Inputs: A0-A11 are sampled during the ACTIVE command (row-address A0-A11) and READ/WRITE command (column-address A0-A9 [x4]; A0-A8 [x8]; A0-A7 [x16]; with A10 defining auto precharge) to select one location out of the memory array in the respective bank. A10 is sampled during a PRECHARGE command to determine if all banks are to be precharged (A10[HIGH]) or bank selected by BA0, BA1 (A1[LOW]). The address inputs also provide the op-code during a LOAD MODE REGISTER command.
2, 4, 5, 7, 8, 10, 11, 13, 42, 44, 45, 47, 48, 50, 51, 53	DQ0-DQ15	x16: I/O	Data Input/Output: Data bus for x16 (4, 7, 10, 13, 42, 45, 48, and 51 are NCs for x8; and 2, 4, 7, 8, 10, 13, 42, 45, 47, 48, 51, and 53 are NCs for x4).
2, 5, 8, 11, 44, 47, 50, 53	DQ0-DQ7	x8: I/O	Data Input/Output: Data bus for x8 (2, 8, 47, 53 are NCs for x4).
5, 11, 44, 50	DQ0-DQ3	x4: I/O	Data Input/Output: Data bus for x4.
40	NC	—	No Connect: These pins should be left unconnected.

36	NC	–	Address input (A12) for the 256Mb and 512Mb devices
3, 9, 43, 49	V _{DDQ}	Supply	DQ Power: Isolated DQ power on the die for improved noise immunity.
6, 12, 46, 52	V _{SSQ}	Supply	DQ Ground: Isolated DQ ground on the die for improved noise immunity.
1, 14, 27	V _{DD}	Supply	Power Supply: +3.3V ±0.3V.
28, 41, 54	V _{SS}	Supply	Ground.

12.28. FLASH 16MBit

12.28.1. Description

The M29W160E is a 16 Mbit (2Mb x8 or 1Mb x16) non-volatile memory that can be read, erased and reprogrammed. These operations can be performed using a single low voltage (2.7 to 3.6V) supply. On power-up the memory defaults to its Read mode where it can be read in the same way as a ROM or EPROM. The memory is divided into blocks that can be erased independently so it is possible to preserve valid data while old data is erased. Each block can be protected independently to prevent accidental Program or Erase commands from modifying the memory. Program and Erase commands are written to the Command Interface of the memory. An on-chip Program/Erase Controller simplifies the process of programming or erasing the memory by taking care of all of the special operations that are required to update the memory contents. The end of a program or erase operation can be detected and any error conditions identified. The command set required to control the memory is consistent with JEDEC standards. The blocks in the memory are asymmetrically arranged, see Figures 5 and 6, Block Addresses. The first or last 64 KBytes have been divided into our additional blocks. The 16 KByte Boot Block can be used for small initialization code to start the microprocessor, the two 8 KByte Parameter Blocks can be used for parameter storage and the remaining 32K is a small Main Block where the application may be stored. Chip Enable, Output Enable and Write Enable signals control the bus operation of the memory. They allow simple connection to most microprocessors, often without additional logic. The memory is offered TSOP48 (12 x 20mm) and TFBGA48 (0.8mm pitch) packages. The memory is supplied with all the bits erased (set to '1').

12.28.2. FEATURES SUMMARY

- SUPPLY VOLTAGE
 - V_{CC} = 2.7V to 3.6V for Program, Erase and Read
- ACCESS TIMES: 70, 90ns
- PROGRAMMING TIME
 - 10µs per Byte/Word typical
- 35 MEMORY BLOCKS
 - 1 Boot Block (Top or Bottom Location)
 - 2 Parameter and 32 Main Blocks
- PROGRAM/ERASE CONTROLLER
 - Embedded Byte/Word Program algorithms
- ERASE SUSPEND and RESUME MODES
 - Read and Program another Block during Erase Suspend
- UNLOCK BYPASS PROGRAM COMMAND
 - Faster Production/Batch Programming
- TEMPORARY BLOCK UNPROTECTION MODE
- COMMON FLASH INTERFACE
 - 64 bit Security Code
- LOW POWER CONSUMPTION
 - Standby and Automatic Standby
- 100,000 PROGRAM/ERASE CYCLES per BLOCK
- ELECTRONIC SIGNATURE
 - Manufacturer Code: 0020h
 - Top Device Code M29W160ET: 22C4h
 - Bottom Device Code M29W160EB: 2249h

12.29. ASM3P2814

12.29.1. Description

The ASM3P28XX devices are versatile spread spectrum frequency modulators designed specifically for a wide range of input clock frequencies from 10MHz to 40MHz.

The ASM3P28XX reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of down stream clock and data dependent signals.

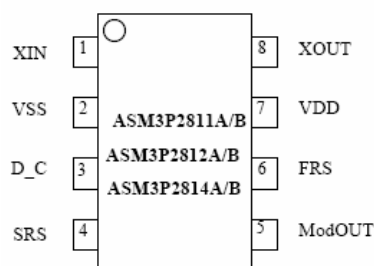
The ASM3P28XX modulates the output of a single PLL in order to “spread” the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal’s bandwidth is called ‘spread spectrum clock generation’.

The ASM3P28XX uses the most efficient and optimized modulation profile approved by the FCC and is implemented in a proprietary all-digital method.

12.29.2. Features

- FCC approved method of EMI attenuation.
- Provides up to 15dB EMI reduction.
- Generates a 1X, 2X and 4X low EMI spread spectrum clock of the input frequency.
- Optimized for input frequency range from 10MHz to 40 MHz.
- Selectable spread options: Down Spread and Center Spread.
- Low inherent cycle-to-cycle jitter.

12.29.3. Pin Descriptions



Pin Description

Pin#	Pin Name	Type	Description
1	XIN	I	Crystal connection or external frequency input. This pin has dual functions. It can be connected to either an external crystal or an external reference clock.
2	VSS	P	Ground to entire chip.
3	D_C	I	Digital logic input used to select Down (LOW) or Center (HIGH) spread options. (Refer Output Frequency Deviation and Spread Option Selection Table). This pin has an internal pull-up resistor.
4	SRS	I	Spread range select. Digital logic input used to select frequency deviation (Refer Output Frequency Deviation and Spread Option Selection Table). This pin has an internal pull-up resistor.
5	ModOUT	O	Spread spectrum clock output (Refer Input/Output Frequency Range Selection Table and Output Frequency Deviation and Spread Option Selection Table).
6	FRS	I	Frequency range select. Digital logic input used to select input frequency range (Refer Input/Output Frequency Deviation and Spread Option Selection Table). This pin has an internal pull-up resistor.
7	VDD	P	Power supply for the entire chip (3.3V).
8	XOUT	I	Crystal connection. Input connection for an external crystal. If using an external reference, this pin must be left unconnected.

12.30. 74LX1G86

12.30.1. Features

- 5V TOLERANT INPUTS
- HIGH SPEED: $t_{PD} = 5\text{ns}$ (MAX.) at $V_{CC} = 3\text{V}$
- LOW POWER DISSIPATION: $I_{CC} = 1\text{A}$ (MAX.) at $T_A = 25^\circ\text{C}$
- POWER DOWN PROTECTION ON INPUTS AND OUTPUTS
- SYMMETRICAL OUTPUT IMPEDANCE: $|I_{OH}| = I_{OL} = 24\text{mA}$ (MIN) at $V_{CC} = 3\text{V}$
- BALANCED PROPAGATION DELAYS: $t_{PLH} \approx t_{PHL}$
- OPERATING VOLTAGE RANGE: $V_{CC}(\text{OPR}) = 1.65\text{V}$ to 5.5V (1.2V Data Retention)
- IMPROVED LATCH-UP IMMUNITY

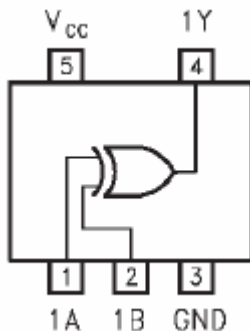
12.30.2. Description

The 74LX1G86 is a low voltage CMOS SINGLE EXCLUSIVE OR GATE fabricated with sub-micron silicon gate and double-layer metal wiring C²MOS technology.

Power down protection is provided on all inputs and 0 to 7V can be accepted on inputs with no regard to the supply voltage. This device can be used to interface 5V to 3V.

All inputs and outputs are equipped with protection circuits against static discharge.

12.30.3. Pin Connections and Descriptions



PIN No	SYMBOL	NAME AND FUNCTION
1	1A	Data Input
2	1B	Data Input
4	1Y	Data Output
3	GND	Ground (0V)
5	V _{CC}	Positive Supply Voltage

12.31. 74HCT4053

12.31.1. General Description

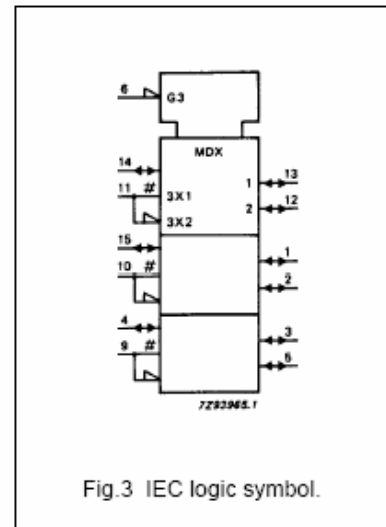
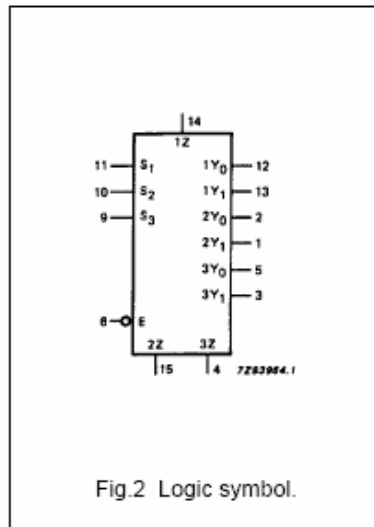
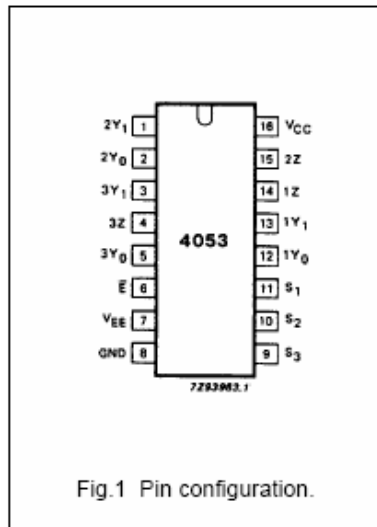
74HCT4053 is a high-speed Si-gate CMOS device, which has a triple 2-channel analogue multiplexer / demultiplexer with a common enable input.

V_{CC} and GND are the supply voltage pins for the digital control inputs. The V_{CC} to GND ranges are 4.5 to 5.5 V for HCT. The analog inputs/outputs (nY_0 and nY_1 , and nZ) can swing between V_{CC} as a positive limit and V_{EE} as a negative limit. $V_{CC} - V_{EE}$ may not exceed 10.0 V.

12.31.2. Pin Description

PIN DESCRIPTION

PIN NO.	SYMBOL	NAME AND FUNCTION
2, 1	$2Y_0$ to, $2Y_1$	independent inputs/outputs
5, 3	$3Y_0$ to, $3Y_1$	independent inputs/outputs
6	$\bar{E}$	enable input (active LOW)
7	V_{EE}	negative supply voltage
8	GND	ground (0 V)
11, 10, 9	S_1 to S_3	select inputs
12, 13	$1Y_0$, $1Y_1$	independent inputs/outputs
14, 15, 4	$1Z$ to $3Z$	common inputs/outputs
16	V_{CC}	positive supply voltage



13. IC DESCRIPTIONS (FOR DIGITAL)

STi5518	24C32
MAX232_SMD	STV0360
74HCU04	MAX809
TSH22	TDCC2345TV39A
CS4334	STV0700
AMIC A43L2616	
MX29LV160T	

13.1. STi5518

13.1.1. General Description

The STi5518 is a highly integrated single-chip decoder, designed for use in feature-rich mass-market set-top boxes. It integrates a high-performance 32-bit CPU, a dedicated block for DVB/DirecTV transport demultiplexing and descrambling, modules for MPEG-2 video and audio decoding with 3D-surround and MP3 support, advanced display and graphics features, a digital video encoder and all of the system peripherals required in a typical low-cost interactive receiver.

To cover the needs of DVD-capable set-top boxes, STi5518 integration options include a CSS decryption block, a Dolby Digital audio decoder and Macrovision copy protection.

An ATAPI interface is built-in, supporting the glueless connection of standard Hard Disk Drives. In this way, the STi5518 is ideal for set-top boxes featuring trick modes such as live TV recording, pausing and time-shifting.

The STi5518 is backward compatible with the popular STi5500 set-top box decoder, allowing easy migration from the previous generation.

The high level of integration in a single PQFP-208 package makes the STi5518 ideally suited for low-cost, high-volume set-top box applications.

13.2. MAX232_SMD

13.2.1. General Description

The MAX220–MAX249 family of line drivers/receivers is intended for all EIA/TIA-232E and V.28/V.24 communications interfaces, particularly applications where $\pm 12V$ is not available.

These parts are especially useful in battery-powered systems, since their low-power shutdown mode reduces power dissipation to less than 5 μ W. The MAX225, MAX233, MAX235, and MAX245/MAX246/MAX247 use no external components and are recommended for applications where printed circuit board space is critical.

13.2.2. Features

- Operate from Single +5V Power Supply (+5V and +12V—MAX231/MAX239)
- Low-Power Receive Mode in Shutdown (MAX223/MAX242)
- Meet All EIA/TIA-232E and V.28 Specifications
- Multiple Drivers and Receivers
- 3-State Driver and Receiver Outputs
- Open-Line Detection (MAX243)

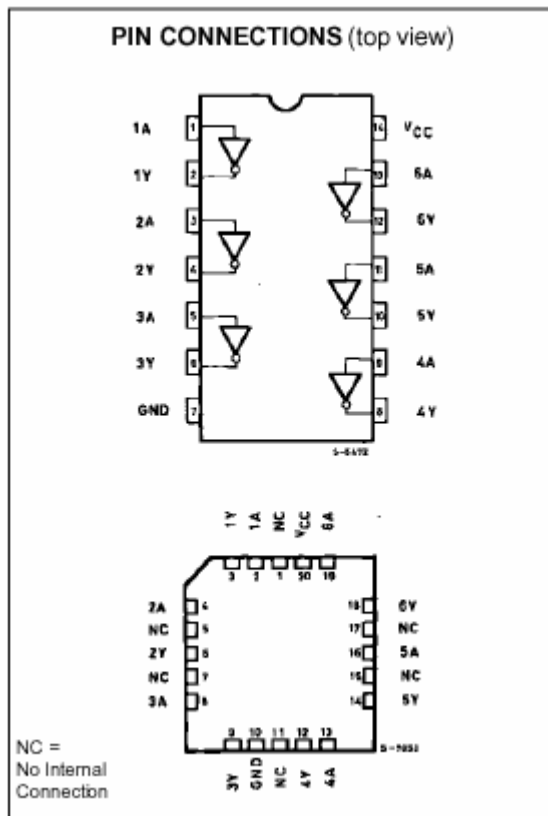
13.3. 74HCU04

13.3.1. General Description

The M54/74HCU04 is a high speed CMOS HEX INVERTER (SINGLE STAGE) fabricated in silicon gate C²MOS technology. It has the same high speed performance of LSTTL combined with true CMOS low power consumption.

As the internal circuit is composed of a single stage inverter, it can be used in crystal oscillator. All inputs are equipped with circuits against static discharge and transient excess voltage.

13.3.2. Pin Description



PIN No	SYMBOL	NAME AND FUNCTION
1, 3, 5, 9, 11, 13	1A to 6A	Data Inputs
2, 4, 6, 8, 10, 12	1Y to 6Y	Data Outputs
7	GND	Ground (0V)
14	V _{CC}	Positive Supply Voltage

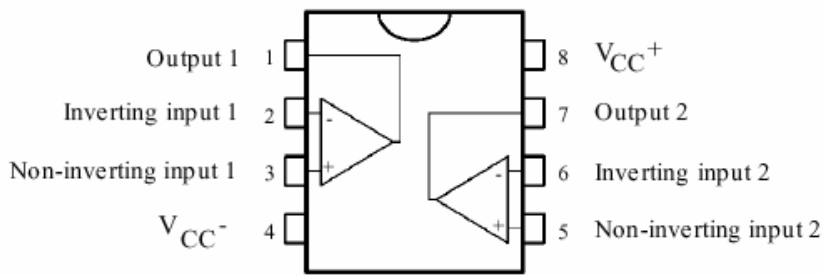
13.4. TSH22

13.4.1. General Description

The TSH22 is a dual bipolar operational amplifier offering a single supply operation from 3V to 30V with very good performances: medium speed (25MHz), unity gain stability and low noise.

The TSH 22 is therefore an enhanced replacement of standard dual operational amplifiers.

13.4.2. Pin Connections



13.5. CS4334

13.5.1. General Description

The CS4334 family members are complete, stereo digital-to-analogue output systems including interpolation, 1-bit D/A conversion and output analogue filtering in an 8-pin package. The CS4334/5/6/7/8/9 support all major audio data interface formats and the individual devices differ only in the supported interface format.

The CS4334 family is based on delta-sigma modulation, where the modulator output controls the reference voltage input to an ultra-linear analogue low-pass filter. This architecture allows for infinite adjustment of sample rate between 2 kHz and 100 kHz simply by changing the master clock frequency. The CS4334 family contains on-chip digital de-emphasis, operates from a single +5V power supply, and requires minimal support circuitry. These features are ideal for portable CD players and other portable playback systems.

13.5.2. Features

- Complete Stereo DAC System: Interpolation, D/A, Output Analogue Filtering
- 24-Bit Conversion
- 96 dB Dynamic Range
- Low Distortion
- Low Clock Jitter Sensitivity
- Single 5 V Power Supply
- Filtered Line Level Outputs
- On-Chip Digital De-emphasis
- Soft Ramp to Quiescent Output Voltage
- Functionally Compatible with CS4330/31/33

13.6. AMIC A43L2616

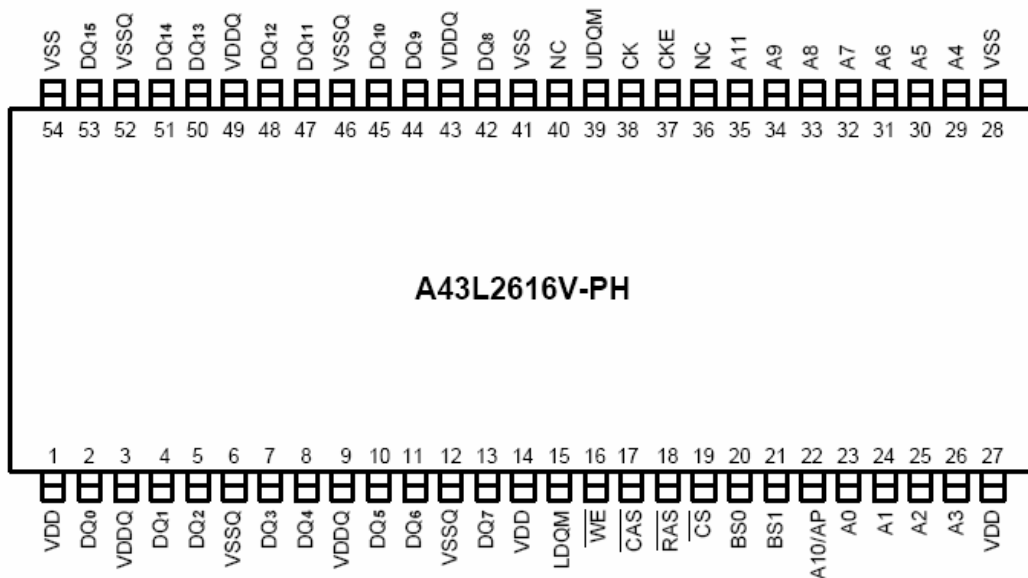
13.6.1. General Description

The A43L2616-PH is 67,108,864 bits synchronous high data rate Dynamic RAM organized as 4 X 1,048,576 words by 16 bits, fabricated with AMIC's high performance CMOS technology. Synchronous design allows precise cycle control with the use of system clock. I/O transactions are possible on every clock cycle. Range of operating frequencies, programmable latencies allows the same device to be useful for a variety of high bandwidth, high performance memory system applications.

13.6.2. Features

- JEDEC standard 3.3V power supply
- LVTTTL compatible with multiplexed address
- Four banks / Pulse RAS
- MRS cycle with address key programs
- All inputs are sampled at the positive going edge of the system clock
- Clock Frequency: 166MHz @ CL=3
143MHz @ CL=3
- Burst Read Single-bit Write operation
- DQM for masking
- Auto & self refresh
- 64ms refresh period (4K cycle)
- 54 Pin TSOP (II)

13.6.3. Pin Description



Symbol	Name	Description
CLK	System Clock	Active on the positive going edge to sample all inputs.
$\overline{\text{CS}}$	Chip Select	Disables or Enables device operation by masking or enabling all inputs except CLK, CKE and L(U)DQM
CKE	Clock Enable	Masks system clock to freeze operation from the next clock cycle. CKE should be enabled at least one clock + tss prior to new command. Disable input buffers for power down in standby.
A0~A11	Address	Row / Column addresses are multiplexed on the same pins. Row address : RA0~RA11, Column address: CA0~CA7
BS0, BS1	Bank Select Address	Selects bank to be activated during row address latch time. Selects band for read/write during column address latch time.
$\overline{\text{RAS}}$	Row Address Strobe	Latches row addresses on the positive going edge of the CLK with $\overline{\text{RAS}}$ low. Enables row access & precharge.
$\overline{\text{CAS}}$	Column Address Strobe	Latches column addresses on the positive going edge of the CLK with $\overline{\text{CAS}}$ low. Enables column access.
$\overline{\text{WE}}$	Write Enable	Enables write operation and Row precharge.
L(U)DQM	Data Input/Output Mask	Makes data output Hi-Z, t SHZ after the clock and masks the output. Blocks data input when L(U)DQM active.
DQ0-15	Data Input/Output	Data inputs/outputs are multiplexed on the same pins.
VDD/VSS	Power Supply/Ground	Power Supply: +3.3V±0.3V/Ground
VDDQ/VSSQ	Data Output Power/Ground	Provide isolated Power/Ground to DQs for improved noise immunity.
NC/RFU	No Connection	

13.7. MX29LV160T

13.7.1. General Description

The MX29LV160T/B & MX29LV160AT/AB is a 16-megabit Flash memory organized as 2M bytes of 8 bits or 1M words of 16 bits. MXIC's Flash memories offer the most cost-effective and reliable read/write non-volatile random access memory. The MX29LV160T/B & MX29LV160AT/AB is packaged in 44-pin SOP, 48-pin TSOP and 48-ball CSP. It is designed to be reprogrammed and erased in system or in standard EPROM programmers.

The standard MX29LV160T/B & MX29LV160AT/AB offers access time as fast as 70ns, allowing operation of high-speed microprocessors without wait states. To eliminate bus contention, the MX29LV160T/B & MX29LV160AT/AB has separate chip enable (CE) and output enable (OE) controls.

MXIC's Flash memories augment EPROM functionality with in-circuit electrical erasure and programming. The MX29LV160T/B & MX29LV160AT/AB uses a command register to manage this functionality. The command register allows for 100% TTL level control inputs and fixed power supply levels during erase and programming, while maintaining maximum EPROM compatibility.

MXIC Flash technology reliably stores memory contents even after 100,000 erase and program cycles. The MXIC cell is designed to optimize the erase and programming mechanisms. In addition, the combination of advanced tunnel oxide processing and low internal electric fields for erase and program operations produces reliable cycling. The MX29LV160T/B & MX29LV160AT/AB uses a 2.7V~3.6V VCC supply to perform the High Reliability Erase and auto Program/Erase algorithms.

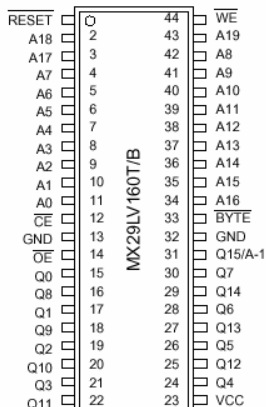
The highest degree of latch-up protection is achieved with MXIC's proprietary non-epi process. Latch-up protection is proved for stresses up to 100 milliamps on address and data pin from -1V to VCC + 1V.

13.7.2. Features

- Extended single - supply voltage range 2.7V to 3.6V
- 2,097,152 x 8/1,048,576 x 16 switchable
- Single power supply operation
- Fast access time: 70/90ns
- Low power consumption
- Command register architecture
- Auto Erase (chip & sector) and Auto Program
- Erase Suspend/Erase Resume
- Status Reply
- Ready/Busy pin (RY/BY)
- Sector protection
- CFI (Common Flash Interface) compliant (for MX29LV160AT/AB)
- 100,000 minimum erase/program cycles
- Latch-up protected to 100mA from -1V to VCC+1V
- Boot Sector Architecture
- Low VCC write inhibit is equal to or less than 1.4V
- Compatibility with JEDEC standard

13.7.3. Pin Description

44 SOP(500 mil)



SYMBOL	PIN NAME
A0~A19	Address Input
Q0~Q14	Data Input/Output
Q15/A-1	Q15(Word mode)/LSB addr(Byte mode)
CE	Chip Enable Input
WE	Write Enable Input
BYTE	Word/Byte Selection input
RESET	Hardware Reset Pin/Sector Protect Unlock
OE	Output Enable Input
RY/BY	Ready/Busy Output
VCC	Power Supply Pin (2.7V~3.6V)
GND	Ground Pin

13.8. 24C32

13.8.1. General Description

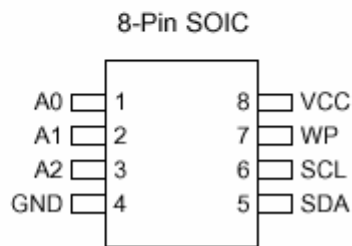
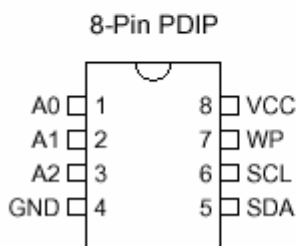
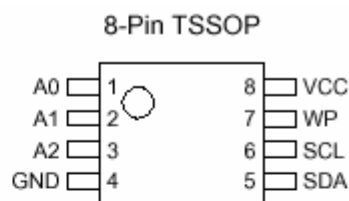
The AT24C32/64 provides 32,768/65,536 bits of serial electrically erasable and programmable read only memory (EEPROM) organized as 4096/8192 words of 8 bits each. The device's cascadable feature allows up to 8 devices to share a common 2-wire bus. The device is optimized for use in many industrial and commercial applications where low power and low voltage operation are essential. The AT24C32/64 is available in space saving 8-pin JEDEC PDIP, 8-pin JEDEC SOIC, 8-pin EIAJ SOIC, and 8-pin TSSOP (AT24C64) packages and is accessed via a 2-wire serial interface. In addition, the entire family is available in 2.7V (2.7V to 5.5V) and 1.8V (1.8V to 5.5V) versions.

13.8.2. Features

- Low-Voltage and Standard-Voltage Operation
- Low-Power Devices ($I_{SB} = 2 \mu A$ at 5.5V) Available
- Internally Organized 4096 x 8, 8192 x 8
- 2-Wire Serial Interface
- Schmitt Trigger, Filtered Inputs for Noise Suppression
- Bidirectional Data Transfer Protocol
- 100 kHz (1.8V, 2.5V, 2.7V) and 400 kHz (5V) Clock Rate
- Write Protect Pin for Hardware Data Protection
- 32-Byte Page Write Mode (Partial Page Writes Allowed)
- Self-Timed Write Cycle (10 ms max)
- High Reliability
- Automotive Grade and Extended Temperature Devices Available
- 8-Pin JEDEC PDIP, 8-Pin JEDEC SOIC, 8-Pin EIAJ SOIC, and 8-pin TSSOP Packages

13.8.3. Pin Description

Pin Name	Function
A0 - A2	Address Inputs
SDA	Serial Data
SCL	Serial Clock Input
WP	Write Protect



SERIAL CLOCK (SCL): The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.

SERIAL DATA (SDA): The SDA pin is bidirectional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or open collector devices.

DEVICE/PAGE ADDRESSES (A2, A1, A0): The A2, A1 and A0 pins are device address inputs that are hard wired or left not connected for hardware compatibility with AT24C16. When the pins are hardwired, as many as eight 32K/64K devices may be addressed on a single bus system (device addressing is discussed in detail under the Device Addressing section). When the pins are not hardwired, the default A₂, A₁, and A₀ are zero.

WRITE PROTECT (WP): The write protect input, when tied to GND, allows normal write operations. When WP is tied high to V_{CC}, all write operations to the upper quadrant (8/16K bits) of memory are inhibited. If left unconnected, WP is internally pulled down to GND.

13.9. STV0360

13.9.1. General Description

The STV0360 is a single-chip COFDM (coded orthogonal frequency division multiplex) demodulator that performs IF to MPEG-2 block processing of OFDM carriers. It is intended for digital terrestrial receivers for compressed video, sound and data services.

The chip implements all the functions from the tuner IF output up to the MPEG-2 transport stream input. The STV0360 is fully compliant with the DVB-T specification (ETS 300 744) and handles 2K/8K modes. The STV0360 integrates an A/D converter that delivers the required performance to handle up to 64 QAM carriers in a direct IF sampling architecture, thus eliminating the need for an external down-converter. The chip also integrates an internal programmable gain amplifier (PGA) to compensate for SAW filter level degradation, thus eliminating the need for external IF amplifiers. A 10-bit ADC, intended for RF signal strength indication, eliminates the need for external components when using wide-band AGC tuners.

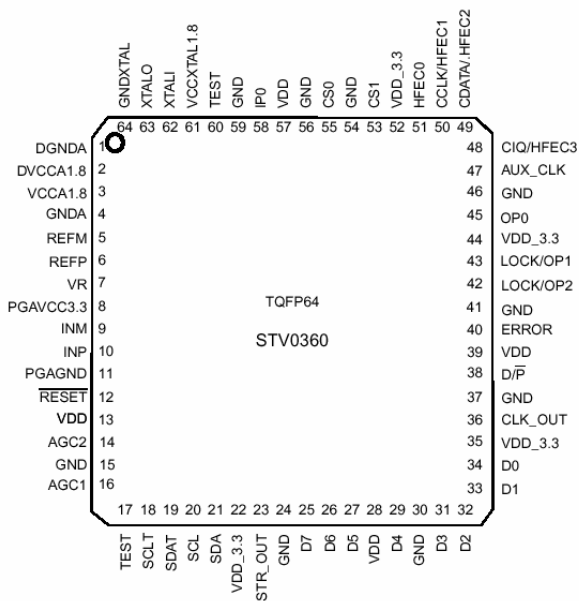
In addition to all the demodulation and FEC (forward error correction) functions required for recovery of the QAM modulated bit streams with very low BER, it also includes several features that give easy and immediate access to various quality monitoring parameters or lock status. The STV0360 also provides output such as delayed AGC or noise-free I²C bus dedicated to tuner control, which facilitates the design of high quality integrated receiver decoders.

The STV0360 outputs error-corrected MPEG-2 transport streams and complies with the DVB common interface format, with programmable data clock frequency. It also interfaces seamlessly with the packet de-multiplexers embedded in the STi55xx Omega family of single-chip decoders.

13.9.2. Features

- Decodes DVB-T (ETS300744) and NorDig II
- TPS decoded or automatic FEC mode detection
- Embeds PGA for IF level adaptation
- Generates system clock on-chip from 20 to 27-MHz crystal quartz
- Four I²C addresses available
- Low power consumption (< 500 mW)
- Small footprint: TQFP64 (10 X 10 mm)
- 1.8 V operation, CMOS technology

13.9.3. Pin Description



VDD_3.3: 3.3V output buffer supply
VDD: 1.8V core and input buffer supply
GND: both core and buffer ground

Pin number	Name	Type	Description	Drive (mA)
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Clock and resets

12	RESET	I ^a	Hardware reset, active low	-
62	XTALI	Analog	Crystal oscillator input/external clock (1.8 V)	-
63	XTALO	Analog	Crystal oscillator output	-
61	VCCXTAL1.8	Supply	Analog oscillator supply (1.8 V)	-
64	GNDXTAL	Ground	Analog oscillator ground	-

Analog interface

2	DVCCA1.8	Supply	Analog part digital supply (1.8 V)	-
5	REFM	Analog	Internal negative reference	-
6	REFP	Analog	Internal positive reference	-
3	VCCA1.8	Supply	Analog supply (1.8 V)	-
9	INM	Analog	Negative analog input	-
10	INP	Analog	Positive analog input	-
4	GNDA	Supply	Analog ground	-
1	DGNDA	Ground	Analog ground	-
7	VR	Analog	Reference	-
11	PGAGND	Supply	PGA ground	-
8	PGAVCC3.3	Supply	PGA VCC (3.3 V)	-

I²C interface

21	SDA	IO ^b	Serial data (open drain)	8
20	SCL	I	Serial clock (open drain)	-
19	SDAT	IO	SDA tuner (open drain)	4
18	SCLT	I	SCL tuner	-

MPEG interface

25, 26, 27, 29, 31, 32, 33, 34	D7/0	O ^c	Serial D7, MPEG data	8/4
36	CLK_OUT	O	MPEG byte or bit clock	4
23	STR_OUT	O	MPEG first byte sync	2
38	D/ $\overline{P}$	O	MPEG data valid/parity	4
40	ERROR	O	MPEG packet error	2
51	HFEC0	O	Hierarchical FEC output bit 0	2
50	CCLK/HFEC1	O	Hierarchical FEC output bit 1 or clock for constellation display	2
49	CDATA/HFEC2	O	Hierarchical FEC output bit 2 or data for constellation display	2
48	CIQ/HFEC3	O	Hierarchical FEC output bit 3 or IQ validation for constellation display	2

Front end controls

16	AGC1	IO	RF AGC control $\Sigma\Delta$	4
14	AGC2	IO	IF AGC control $\Sigma\Delta$	4
17, 60	TEST		Reserved test mode, must be grounded	
58	IP0	I	General purpose input port 0 and ADC input for RF level monitoring	-
45	OP0	IO	General purpose output port 0	4
43	LOCK/OP1	IO	General purpose output port 1 or lock indicator	4
42	LOCK/OP2	O	General purpose output port 2 or lock indicator	4
47	AUX_CLK	IO	Auxiliary clock	8
55	CS0	I	Chip select LSB	-
53	CS1	I	Chip select MSB	-

Power supply

13, 28, 39, 57	VDD	Supply	Digital core supply	
22, 35, 44, 52	VDD_3.3	Supply	Digital IO supply	
15, 24, 30, 37, 41, 46, 54, 56, 59	GND	Ground		

- a. All inputs are 3.3 V compatible
- b. All bidirectional pads are 3.3 V capable
- c. All outputs are 3.3 V capable

13.10. MAX809

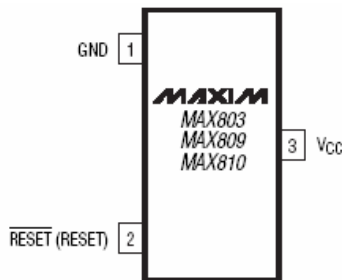
13.10.1. General Description

The MAX803/MAX809/MAX810 are microprocessor (μ P) supervisory circuits used to monitor the power supplies in μ P and digital systems. They provide excellent circuit reliability and low cost by eliminating external components and adjustments when used with +5V, +3.3V, +3.0V, or +2.5V powered circuits. These circuits perform a single function: they assert a reset signal whenever the V_{CC} supply voltage declines below a preset threshold, keeping it asserted for at least 140ms after V_{CC} has risen above the reset threshold. Reset thresholds suitable for operation with a variety of supply voltages are available. The MAX803 has an open-drain output stage, while the MAX809/MAX810 have push-pull outputs. The MAX803's open-drain RESET output requires a pull-up resistor that can be connected to a voltage higher than V_{CC} . The MAX803/MAX809 have an active-low RESET output, while the MAX810 has an active-high RESET output. The reset comparator is designed to ignore fast transients on V_{CC} , and the outputs are guaranteed to be in the correct logic state for V_{CC} down to 1V. Low supply current makes the MAX803/MAX809/MAX810 ideal for use in portable equipment. The MAX803 is available in a 3-pin SC70 package, and the MAX809/MAX810 are available in 3-pin SC70 or SOT23 packages.

13.10.2. Features

- 1 Precision Monitoring of +2.5V, +3V, +3.3V, and +5V Power-Supply Voltages
- Fully Specified Over Temperature
- Available in Three Output Configurations
 - Open-Drain RESET Output (MAX803)
 - Push-Pull RESET Output (MAX809)
 - Push-Pull RESET Output (MAX810)
- 140ms min Power-On Reset Pulse Width
- 12 μ A Supply Current
- Guaranteed Reset Valid to $V_{CC} = +1V$
- Power Supply Transient Immunity
- No External Components
- 3-Pin SC70 and SOT23 Packages

13.10.3. Pin Description



SC70-3/SOT23-3

() ARE FOR MAX810.
MAX803 AVAILABLE IN SC70-3 ONLY.

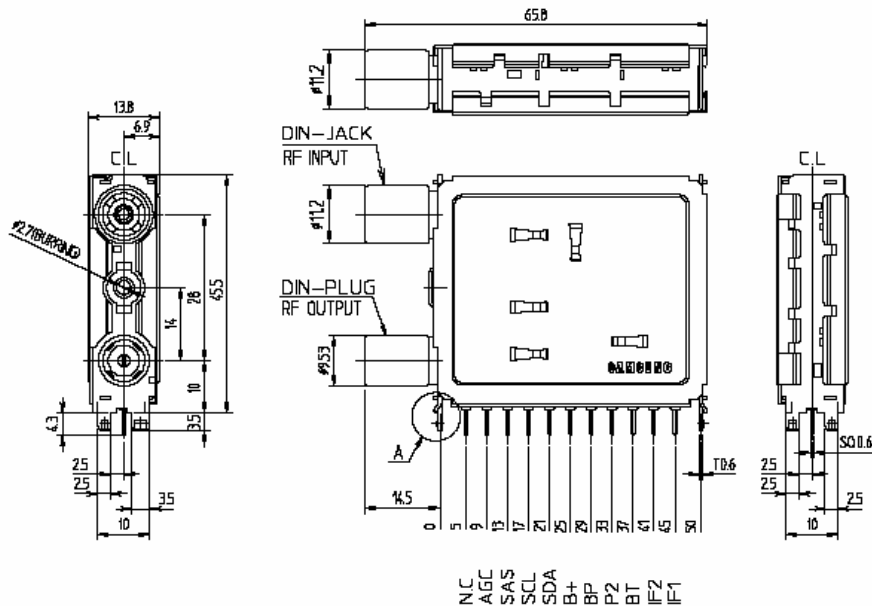
PIN	NAME	FUNCTION
1	GND	Ground
2	RESET (MAX803/ MAX809)	RESET Output remains low while V_{CC} is below the reset threshold, and for at least 140ms after V_{CC} rises above the reset threshold.
	RESET (MAX810)	RESET Output remains high while V_{CC} is below the reset threshold, and for at least 140ms after V_{CC} rises above the reset threshold.
3	V_{CC}	Supply Voltage (+5V, +3.3V, +3.0V, or +2.5V)

13.11. TDCC2345TV39A

13.11.1. General Description

- Receiving System : Designed to cover all bands in VHF and UHF including digital terrestrial channels for DVB-T system.
- Receiving Channel : 47 MHz ~ 862 MHz
- Intermediate Frequency : Digital (center) 36.125 MHz
- Input Impedance : 75Ω, Unbalanced.
- IF Output Impedance : 75Ω, Balanced.
- Loop through RF output Impedance : 75Ω, Unbalanced.
- Band Change-Over System : PLL system
- Tuning System : PLL system
- Pin-out for the port to control the switchable saw

13.11.2. Pin Description



PIN	CONNECTION
1	N.C
2	AGC
3	SAS
4	SCL
5	SDA
6	B+ (for preamp)
7	BP
8	P2 Port (For S/W)
9	BT
10	IFOUT2
11	IFOUT1
12	RF INPUT
13	RF OUTPUT

13.12. STV0700

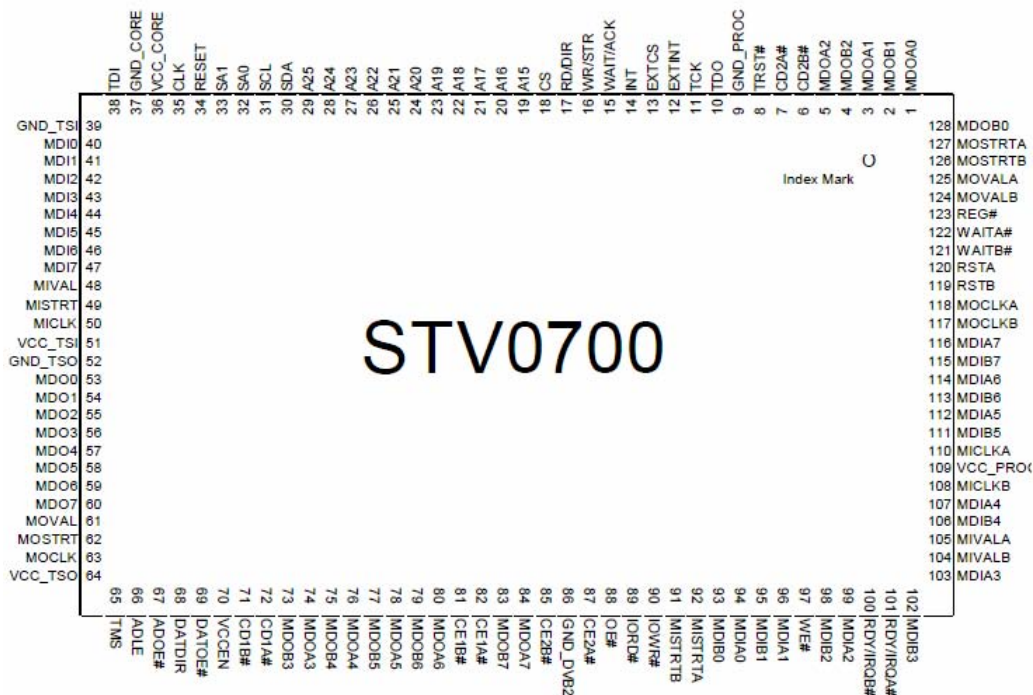
13.12.1. General description

The STV0700 controller contributes to offer an optimized, homogeneous and complete solution for digital TV receiver and Set Top Box manufacturers that want to quickly implement the Common Interface. The STV0700 includes the necessary I/Os to interface to the MPEG Transport stream generated by the receiver demodulator and daisy chain it through two independent Common Interface modules and back to the demultiplexer. The STV0700 interfaces with major digital TV receiver microprocessors. An I²C bus is used for initialization and module selection, while a Universal Control Signal Generator (UCSG) maps CPU control bus into Command Interface control signals. To minimize pin count, host address and data buses transit through external buffers that are driven by the STV0700. The STV0700 includes a memory mode that allows the use any of the Common Interface slots to read and write an 8-bit PC Card Memory card. This feature gives the receiver memory extension capability for software upgrade or better performance.

13.12.2. Features

- Module Interface
 - 2 independent module capability
 - Common Interface Standard compliant
 - o DVB_CI (CENELEC EN-50221)
 - o NRSS-B (SCTE IS-679 Part B)
 - o DAVIC v1.2 (CA0 interface)
 - Memory PCMCIA compliance (R2)
 - o 8-bit data access
 - o 26-bit address Memory Card
 - Attribute Memory access (CIS, Tupple)
 - High speed capability
 - o Up to 20Mbps/s on Command Interface
 - o Up to 100Mbps/s on Transport Stream
 - Polling and Interrupt modes
 - Hot Insertion (Automatic and Reset VCC handling)
 - 3.3V (5V tolerant) I/O buffers
- IEEE 1149.1 Boundary Scan Compliant Test Access Port
- Host microprocessor Interface
 - Universal Control Signal Generator(UCSG)
 - o PC Card control signals generation
 - o Supports PowerPC, ARM, ST20,68xxx, TMS, LSI 64008, TC81220F,IDTR3041 host microprocessors
 - I²C port
 - o STV0700 Set-up
 - o Slot selection
 - o Cascade mode management (up to 4STV0700)
 - Chip Select bank and Interrupt facilities
 - 3.3V (5V tolerant) I/O buffers
- Digital Video Stream Interface
 - MPEG II Transport Stream compliant(serial/parallel configurable interface)
 - 3.3V (5V tolerant) I/O buffer for direct interface with FEC and DEMUX ICs

13.12.3. Pin Description



Host microprocessor interface (24 pins)

Name	I/O	Type	RST	Function
RESET	I	TTL		STV0700 reset
CLK	I	TTL		27MHz clock input
SA1	I	TTL		I ² C address bit 2
SA0	I	TTL		I ² C address bit 1
SCL	I	TTL trig		I ² C clock
SDA	I/O	TTL trig	Z	I ² C data
A25	I	TTL		Host microprocessor address bit 25
A24	I	TTL		Host microprocessor address bit 24
A23	I	TTL		Host microprocessor address bit 23
A22	I	TTL		Host microprocessor address bit 22
A21	I	TTL		Host microprocessor address bit 21
A20	I	TTL		Host microprocessor address bit 20
A19	I	TTL		Host microprocessor address bit 19
A18	I	TTL		Host microprocessor address bit 18
A17	I	TTL		Host microprocessor address bit 17
A16	I	TTL		Host microprocessor address bit 16
A15	I	TTL		Host microprocessor address bit 15
CS	I	TTL		STV0700 chip select input
RD/DIR	I	TTL		Read strobe / transfer direction input
WR/STR	I	TTL		Write strobe / transfer strobe
WAIT/ACK	O	TTL 3-state	Z	WAIT / transfer acknowledge
INT	O	TTL 3-state	Z	Interrupt output to host microprocessor
EXTCS	O	TTL 3-state	Z	External device chip select
EXTINT	I	TTL		External device interrupt input

IEEE 1149.1 Interface (5 pins)

Name	I/O	Type	RST	Function
TCK	I	TTL trig		JTAG test clock
TMS	I	TTL up		JTAG test mode select
TDI	I	TTL up		JTAG test data in
TRST#	I	TTL up		JTAG test reset
TDO	O	TTL 3-state	Z	JTAG test data out

Host TS interface (22 pins)

Name	I/O	Type	RST	Function
MICLK	I	TTL		MPEG clock input from front-end
MISTR	I	TTL		MPEG packet start input (scan in)
MIVAL	I	TTL		MPEG valid data input (scan enable)
MDI7	I	TTL		MPEG data input bit 7
MDI6	I	TTL		MPEG data input bit 6
MDI5	I	TTL		MPEG data input bit 5
MDI4	I	TTL		MPEG data input bit 4
MDI3	I	TTL		MPEG data input bit 3
MDI2	I	TTL		MPEG data input bit 2
MDI1	I	TTL		MPEG data input bit 1

MDI0	I	TTL		MPEG data input bit 0 (Serial data in)
MOCLK	O	TTL 3-state	0	MPEG clock output to MPEG decoder
MOSTRT	O	TTL 3-state	0	MPEG packet start output
MOVAL	O	TTL 3-state	0	MPEG valid data output
MDO7	O	TTL 3-state	0	MPEG data output bit 7
MDO6	O	TTL 3-state	0	MPEG data output bit 6
MDO5	O	TTL 3-state	0	MPEG data output bit 5
MDO4	O	TTL 3-state	0	MPEG data output bit 4
MDO3	O	TTL 3-state	0	MPEG data output bit 3
MDO2	O	TTL 3-state	0	MPEG data output bit 2
MDO1	O	TTL 3-state	0	MPEG data output bit 1
MDO0	O	TTL 3-state	0	MPEG data output bit 0 (Serial data out)

Modules TS interface (44 pins)

Name	I/O	Type	RST	Function
MICLKA	O	TTL 3-state	Z	Module A MPEG clock input
MISTRTA	O	TTL 3-state	Z	Module A MPEG packet start input
MIVALA	O	TTL 3-state	Z	Module A MPEG valid data input
MDIA7	O	TTL 3-state	Z	Module A MPEG data input bit 7
MDIA6	O	TTL 3-state	Z	Module A MPEG data input bit 6
MDIA5	O	TTL 3-state	Z	Module A MPEG data input bit 5
MDIA4	O	TTL 3-state	Z	Module A MPEG data input bit 4
MDIA3	O	TTL 3-state	Z	Module A MPEG data input bit 3
MDIA2	O	TTL 3-state	Z	Module A MPEG data input bit 2
MDIA1	O	TTL 3-state	Z	Module A MPEG data input bit 1
MDIA0	O	TTL 3-state	Z	Module A MPEG data input bit 0
MOCLKA	I	TTL		Module A MPEG clock output to MPEG decoder
MOSTRTA	I	TTL		Module A MPEG packet start output
MOVALA	I	TTL		Module A MPEG valid data output
MDOA7	I	TTL		Module A MPEG data output bit 7
MDOA6	I	TTL		Module A MPEG data output bit 6
MDOA5	I	TTL		Module A MPEG data output bit 5
MDOA4	I	TTL		Module A MPEG data output bit 4
MDOA3	I	TTL		Module A MPEG data output bit 3
MDOA2	I	TTL		Module A MPEG data output bit 2
MDOA1	I	TTL		Module A MPEG data output bit 1
MDOA0	I	TTL		Module A MPEG data output bit 0
MICLKB	O	TTL 3-state	Z	Module B MPEG clock input
MISTRTB	O	TTL 3-state	Z	Module B MPEG packet start input
MIVALB	O	TTL 3-state	Z	Module B MPEG valid data input
MDIB7	O	TTL 3-state	Z	Module B MPEG data input bit 7
MDIB6	O	TTL 3-state	Z	Module B MPEG data input bit 6
MDIB5	O	TTL 3-state	Z	Module B MPEG data input bit 5
MDIB4	O	TTL 3-state	Z	Module B MPEG data input bit 4
MDIB3	O	TTL 3-state	Z	Module B MPEG data input bit 3
MDIB2	O	TTL 3-state	Z	Module B MPEG data input bit 2
MDIB1	O	TTL 3-state	Z	Module B MPEG data input bit 1
MDIB0	O	TTL 3-state	Z	Module B MPEG data input bit 0
MOCLKB	I	TTL		Module B MPEG clock output to MPEG decoder
MOSTRTB	I	TTL		Module B MPEG packet start output
MOVALB	I	TTL		Module B MPEG valid data output

MDOB7	I	TTL		Module B MPEG data output bit 7
MDOB6	I	TTL		Module B MPEG data output bit 6
MDOB5	I	TTL		Module B MPEG data output bit 5
MDOB4	I	TTL		Module B MPEG data output bit 4
MDOB3	I	TTL		Module B MPEG data output bit 3
MDOB2	I	TTL		Module B MPEG data output bit 2
MDOB1	I	TTL		Module B MPEG data output bit 1
MDOB0	I	TTL		Module B MPEG data output bit 0

Modules command interface (24 pins)

Name	I/O	Type	RST	function
RSTA	O	TTL 3-state	Z	Module A reset
CD1A#	I	TTL trig up		Module A card detect 1
CD2A#	I	TTL trig up		Module A card detect 2
CE1A#	O	TTL 3-state	Z	Module A card enable 1
CE2A#	O	TTL 3-state	Z	Module A card enable 2
RDY/IRQA#	I	TTL		Module A Ready / IRQ signal
WAITA#	I	TTL		Module A WAIT# signal
RSTB	O	TTL 3-state	Z	Module B reset (Internal scan out)
CD1B#	I	TTL trig up		Module B card detect 1
CD2B#	I	TTL trig up		Module B card detect 2
CE1B#	O	TTL 3-state	Z	Module B card enable 1
CE2B#	O	TTL 3-state	Z	Module B card enable 2
RDY/IRQB#	I	TTL		Module B Ready / IRQ signal
WAITB#	I	TTL		Module B WAIT# signal
REG#	O	TTL 3-state	Z	Modules REG# signal
OE#	O	TTL 3-state	Z	Modules output enable
WE#	O	TTL 3-state	Z	Modules write enable
IORD#	O	TTL 3-state	Z	Modules I/O read
IOWR#	O	TTL 3-state	Z	Modules I/O write
VCCEN	O	TTL 3-state	Z	Modules VCC switch control
DATOE#	O	TTL 3-state	1	External data buffers output enable
DATDIR	O	TTL 3-state	0	External data buffer direction
ADOE#	O	TTL 3-state	1	External address buffer output enable
ADLE	O	TTL 3-state	1	External address buffer latch enable

Power supply (9 pins)

Name	I/O	Type	Function
VCC_CORE		VDDI	Core Power
VCC_TSI		VDDE	I/O Power
VCC_TSO		VDDE	I/O Power
VCC_PROC		VDDE	I/O Power
GND_DVB2		VSSI	Core Ground
GND_CORE		VSSI	Core Ground
GND_TSI		VSSE	I/O Ground
GND_TSO		VSSE	I/O Ground
GND_PROC		VSSE	I/O Ground

14. SERVICE MENU SETTINGS

All system, geometry and white balance alignments are performed in production service mode. Before starting the production mode alignments, make sure that all manual adjustments are done correctly. To start production mode alignments enter the MENU by pressing “**MENU**” button and then press the digits 4, 7, 2 and 5 respectively. The following menu appears on the screen.

				
display				
blank color	black	red	green	blue
panel				
power on time	:	23 30		
backlight on time	:	23 30		
Vestel V1.0.10 Release Build				
scart prescale				25
nicam prescale				32

down to change display settings

There are 4 submenus in service menu. These are **display**, **calibration**, **deinterlacer** and **factory settings** menus. Press “◀/▶” buttons to select a menu title and then “▲/▼” buttons to select a menu item and “◀/▶” or “OK” buttons to set the menu item to the desired option. To exit the service menu press “**MENU**” button.

Entire service menu parameters of Plasma TV are listed below.

14.1. display menu

By pressing “◀/▶” buttons select the first icon. **display** menu appears on the screen.

				
display				
blank color	black	red	green	blue
panel				
power on time	:	23 30		
backlight on time	:	23 30		
Vestel V1.0.10 Release Build				
scart prescale				25
nicam prescale				32

down to change display settings

blank color

By pressing ▲/▼ button, select **blank color**. Press ◀/▶ button to set the blank color. The options are: **black**, **red**, **green** and **blue**.

panel

Displays panel resolution.

power on time

Displays total working time of the set.

backlight on time

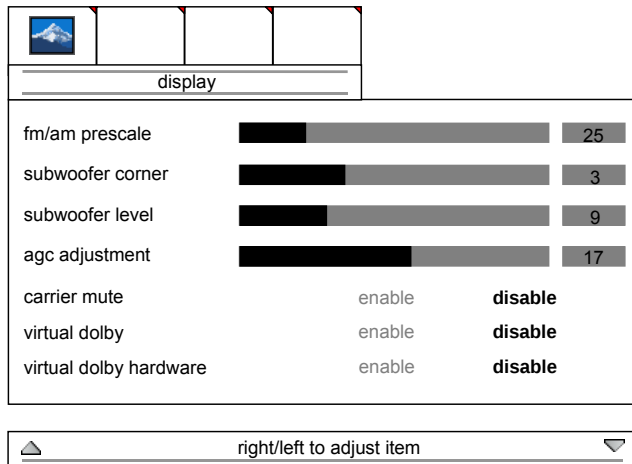
Displays total backlight on time of the set. (Not used for plasma displays)

scart prescale

By pressing ▲/▼ button, select **scart prescaler**. Press ◀/▶ button to set the scart prescaler. Scart prescale can be adjusted between 0 and 127.

nicam prescale

By pressing ▲/▼ button, select **nicam prescaler**. Press ◀/▶ button to set the nicam prescaler. Nicam prescale can be adjusted between 0 and 127.



fm/am prescale

By pressing ▲/▼ button, select **fm/am prescaler**. Press ◀/▶ button to set the fm/am prescaler. Fm/am prescale can be adjusted between 0 and 127.

subwoofer corner

By pressing ▲/▼ button, select **subwoofer corner**. Press ◀/▶ button to set the subwoofer corner. Subwoofer corner can be adjusted between 0 and 7.

subwoofer level

By pressing ▲/▼ button, select **subwoofer level**. Press ◀/▶ button to set the subwoofer level. Subwoofer level can be adjusted between 0 and 32.

agc adjustment

Adjustment for automatic gain control of tuner. By pressing ▲/▼ button, select **agc adjustment**. Press ◀/▶ button to set the agc adjustment. Agc adjustment can be adjusted between 0 and 31.

carrier mute

By pressing ▲/▼ button, select **carrier mute**. Press ◀/▶ button to enable or disable the sound carrier mute feature.

virtual dolby

By pressing ▲/▼ button, select **virtual dolby**. Press ◀/▶ button to enable or disable the virtual dolby feature in the audio menu of the TV.

virtual dolby hardware

By pressing ▲/▼ button, select **virtual dolby hardware**. Press ◀/▶ button to enable or disable the virtual dolby hardware feature of the TV.

14.2. calibration menu

By pressing “◀/▶” buttons select the second icon. **calibration** menu appears on the screen.

calibration	
initial APS	on off
burn-in mode	on off
color temp	5500K 6500K 7500K 9300K user
R	
G	
B	
video format	auto

down to change cal. settings, scrolling menu

initial APS

By pressing ▲/▼ button, select **initial APS**. Initial APS can be selected **on** or **off**. If initial aps is switched on, then the TV will display initial APS menu only for the first time it is switched on.

burn-in mode

By pressing ▲/▼ button, select **burn-in mode**. Press ◀/▶ button to set it on or off.

color temp

By pressing ▲/▼ button, select **color temp**. Press ◀/▶ button to set the color temperature. The options are: **5500K**, **6500K**, **7500K**, **9300K** and **user**.

R/G/B

If **color temp** is set as “user”, then R/G/B settings can be adjusted. By pressing ▲/▼ button, select **Red**, **Green** or **Blue**. Press ▶ button to increase the color value. Press ◀ button to decrease the color value. R/G/B values can be adjusted between 0 and 63.

video format

By pressing ▲/▼ button, select **video format**. Press ◀/▶ button to set the video format. The options are: **auto**, **ntsc**, **pal**, **secam** and **ntsc japan**.

calibration	
colorspace	RGB
test pattern	none solid color vert bars
color components	all red green blue
solid field level	33
factory reset	<ok> to activate
main tuner	Tuner 1
pip tuner	Tuner 1
teletext language	on off

right/left to adjust item

color space

Displays the current color space used. **RGB**, **YPbPr SMPTE240**, **YPbPr REC709** and **YCbCr REC601**.

test pattern

By pressing ▲/▼ button, select **test pattern**. Press ◀/▶ button to set the test pattern. The options are: **none**, **solid color** and **vert bars**.

color components

By pressing ▲/▼ button, select **color components**. Press ◀/▶ button to set the color components. The options are: **all**, **red**, **green** and **blue**.

solid field level

By pressing ▲/▼ button, select **solid field level**. Press ► button to increase or ◀ button to decrease the solid field level. Solid field level can be adjusted between 0 and 64.

factory reset

By pressing ▲/▼ button, select **factory reset**. Press “OK” button to return to the factory setting values.

main tuner

By pressing ▲/▼ button, select **main tuner**. Press ◀/▶ button to set a tuner as main tuner.

pip tuner

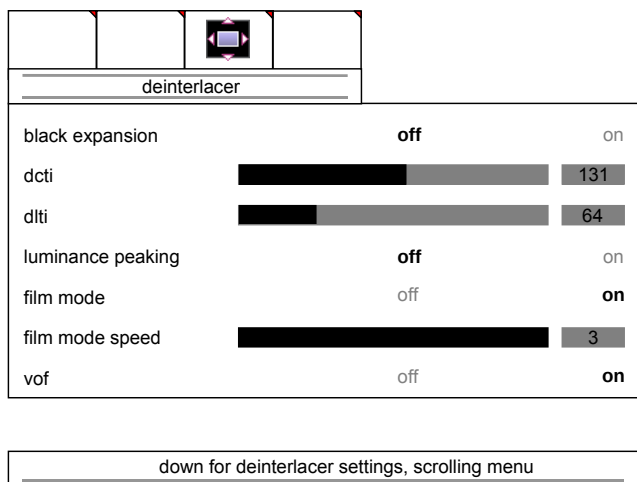
By pressing ▲/▼ button, select **pip tuner**. Press ◀/▶ button to set a tuner as pip tuner.

teletext language

By pressing ▲/▼ button, select **teletext language**. Press ◀/▶ button to set it on or off. When it is turned on, the teletext language option can be seen in the TV menu.

14.3. deinterlacer menu

By pressing “◀/▶” buttons select the third icon. **deinterlacer** menu appears on the screen.



black expansion

By pressing ▲/▼ button, select **black expansion**. Black expansion can be set to **on** or **off** by pressing ◀/▶ button.

dcti

Digital colour transition improvement: By pressing ▲/▼ button, select **dcti**. DCTI can be adjusted between **0** and **255** by pressing ◀/▶ button.

dlti

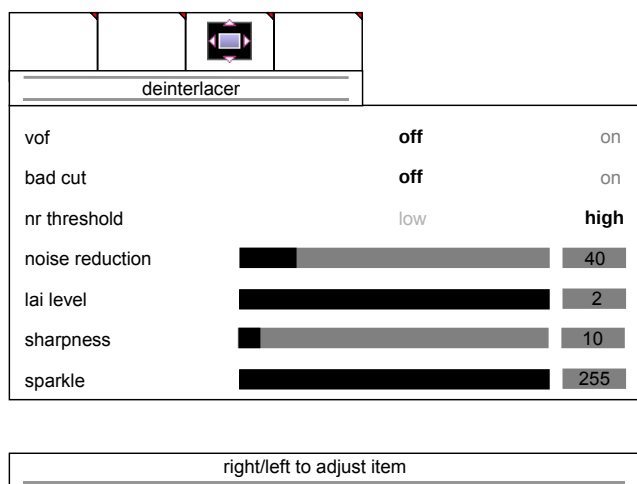
Digital luma transition improvement: By pressing ▲/▼ button, select **dlti**. DLTI can be adjusted between **0** and **255** by pressing ◀/▶ button.

luminance peaking

By pressing ▲/▼ button, select **luminance peaking**. Luminance peaking can be set to **on** or **off** by pressing ◀/▶ button.

film mode

By pressing ▲/▼ button, select **film mode**. Film mode speed can be set to **on** or **off** by pressing ◀/▶ button.



film mode speed

By pressing ▲/▼ button, select **film mode speed**. Film mode speed can be set to **0**, **1**, **2** or **3** by pressing ◀/▶ button.

vof

video on film. By pressing ▲/▼ button, select **vof**. VOF can be set to **on** or **off** by pressing ◀/▶ button.

bad cut

By pressing ▲/▼ button, select **vof**. Bad cut can be set to **on** or **off** by pressing ◀/▶ button.

nr threshold

By pressing ▲/▼ button, select **nr threshold**. Nr threshold can be set to **low** or **high** by pressing ◀/▶ button.

noise reduction

By pressing ▲/▼ button, select **noise reduction**. Noise reduction can be adjusted between **0** and **255** by pressing ◀/▶ button.

lai level

By pressing ▲/▼ button, select **lai level**. Lai level can be set to **0**, **1** or **2** by pressing ◀/▶ button.

sharpness

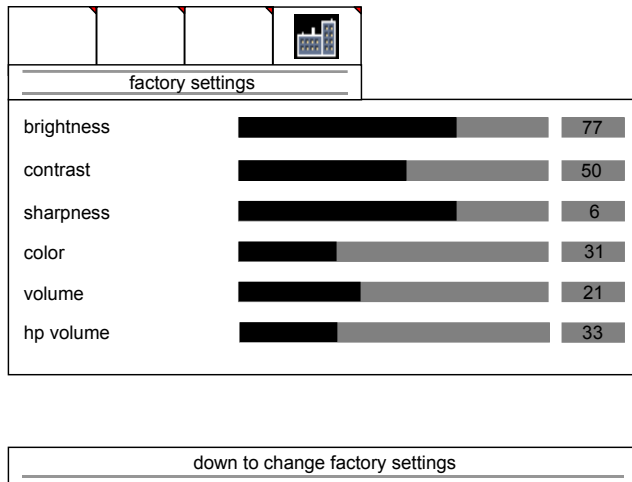
By pressing ▲/▼ button, select **sharpness**. Sharpness can be adjusted between **0** and **255** by pressing ◀/▶ button.

sparkle

By pressing ▲/▼ button, select **sparkle**. Sparkle can be adjusted between **0** and **255** by pressing ◀/▶ button.

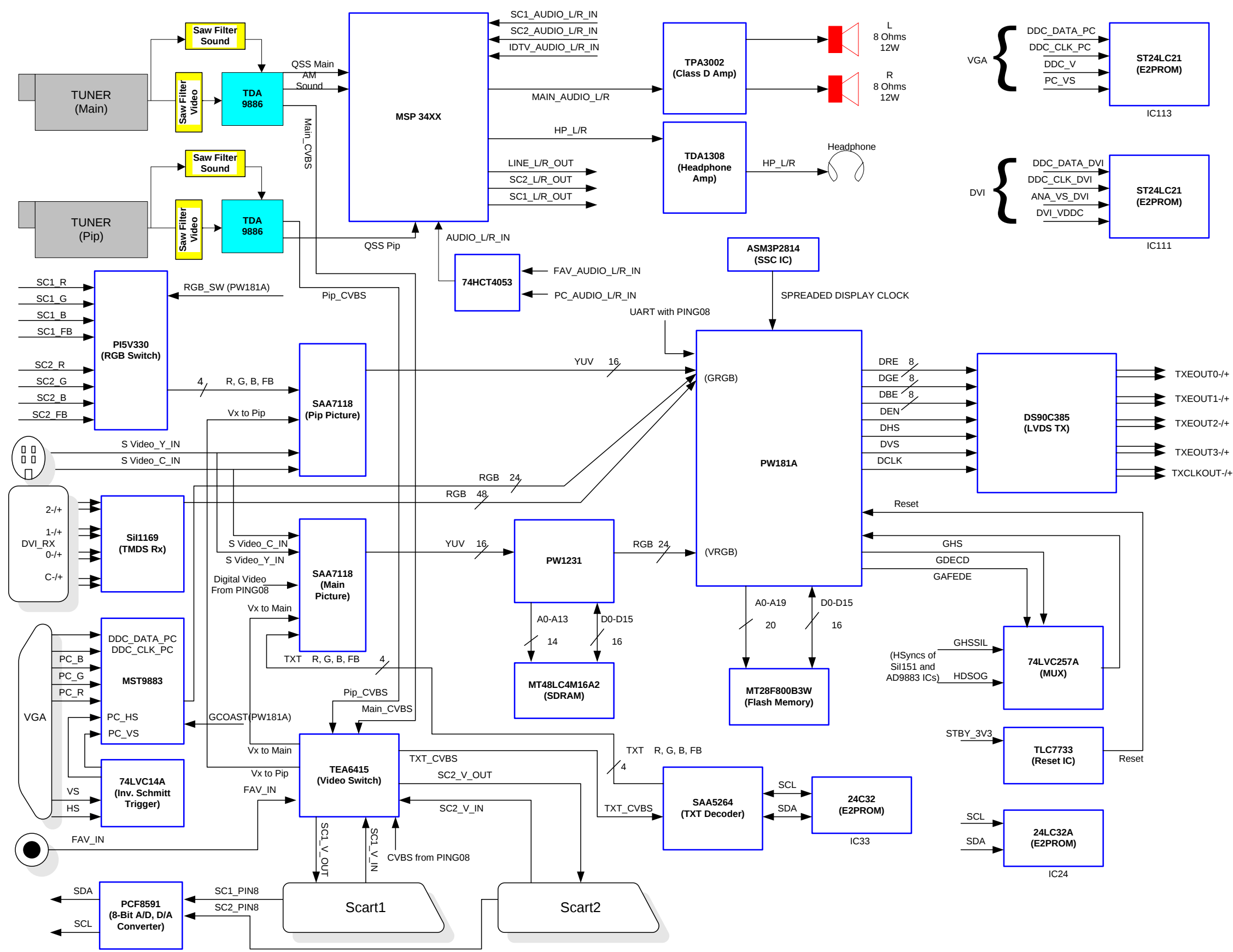
14.4. factory settings menu

By pressing “◀/▶” buttons select the fourth icon. **Factory settings** menu appears on the screen.

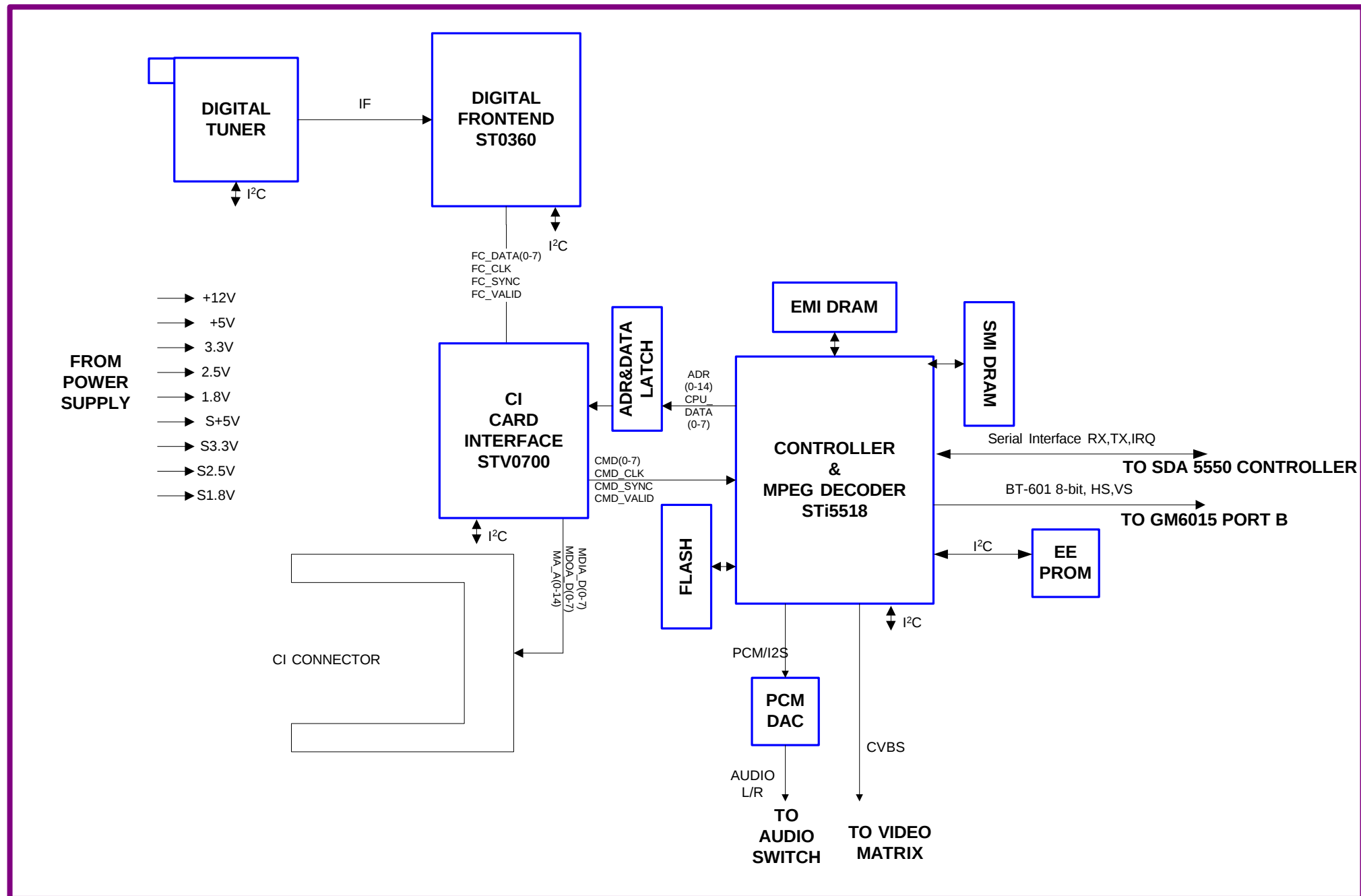


Brightness, contrast, sharpness, color, volume and **headphone volume** factory settings can be seen in this menu. When factory reset is selected in the calibration menu, the values in the factory settings menu will be seen in the TV menus.

15.BLOCK DIAGRAMS

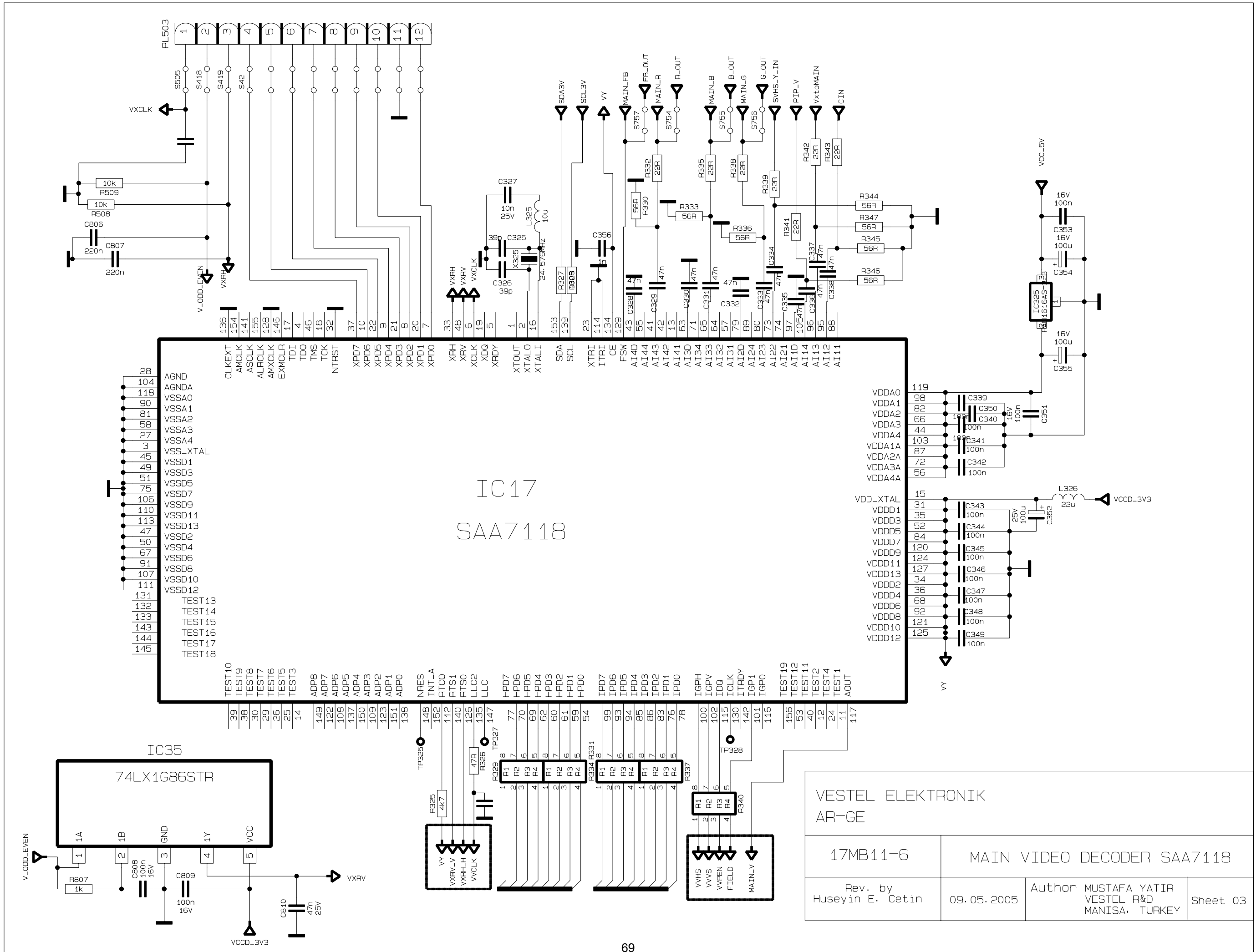


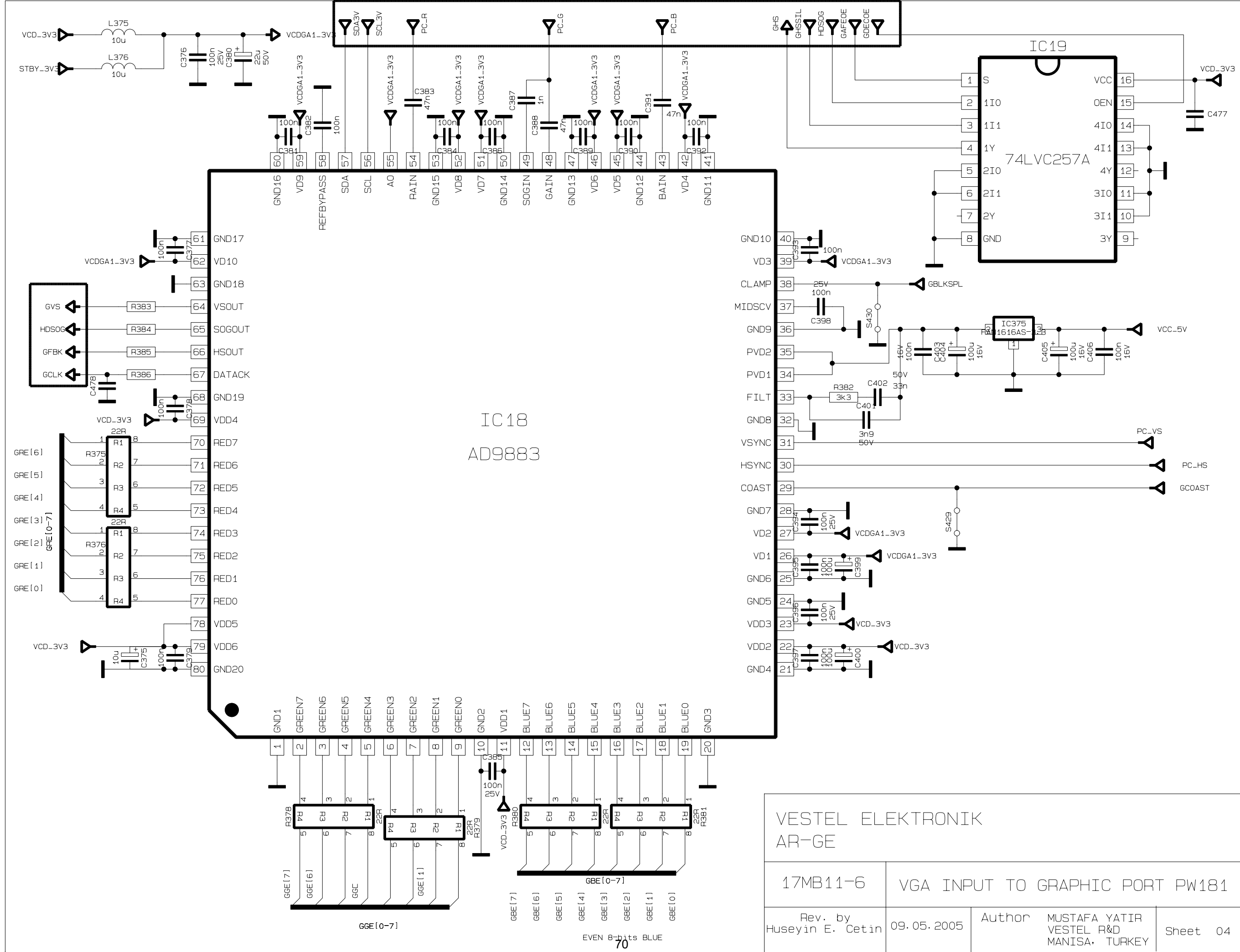
BLOCK DIAGRAM - IDTV PART

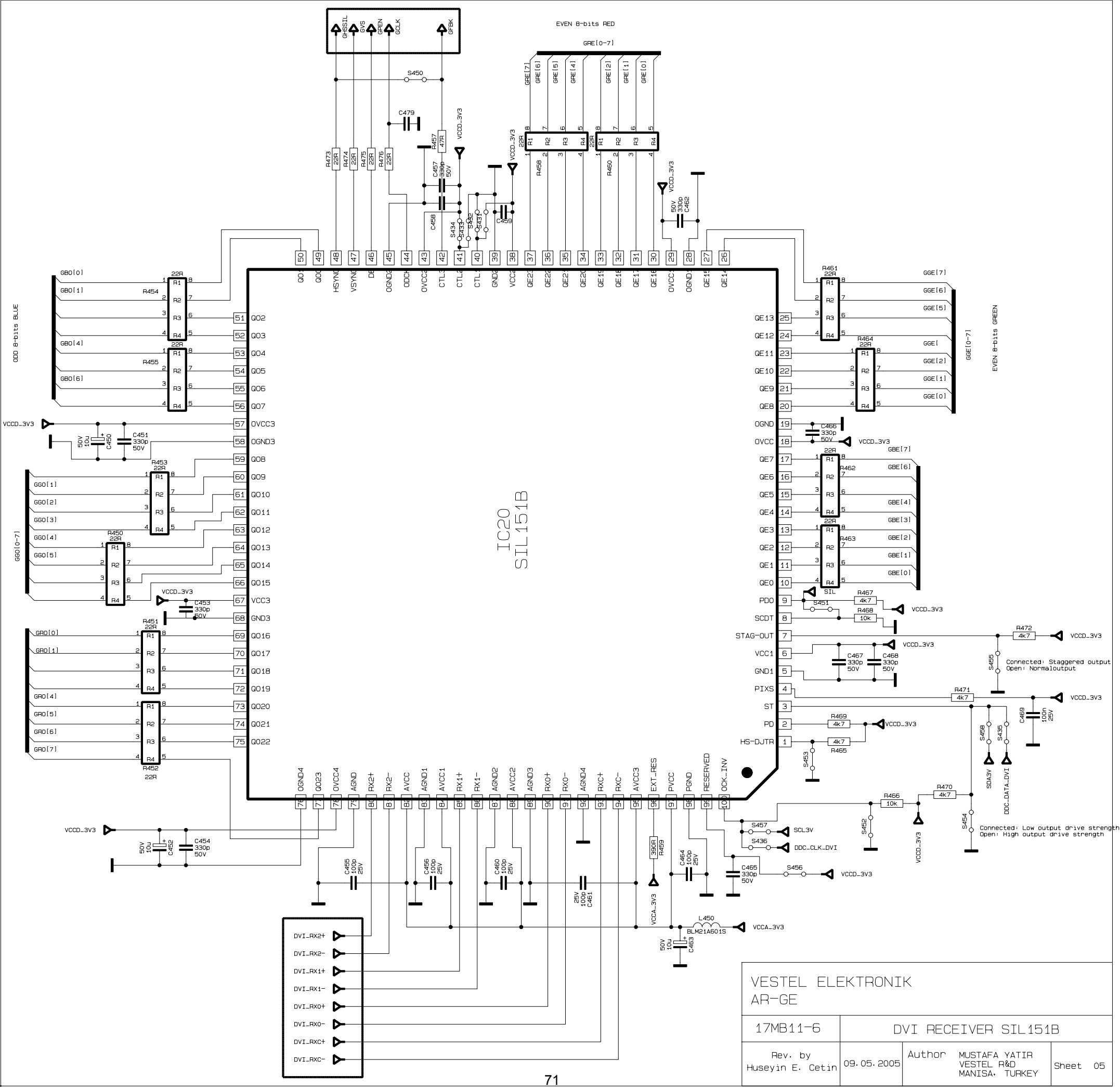


27" TFT TV Service Manual









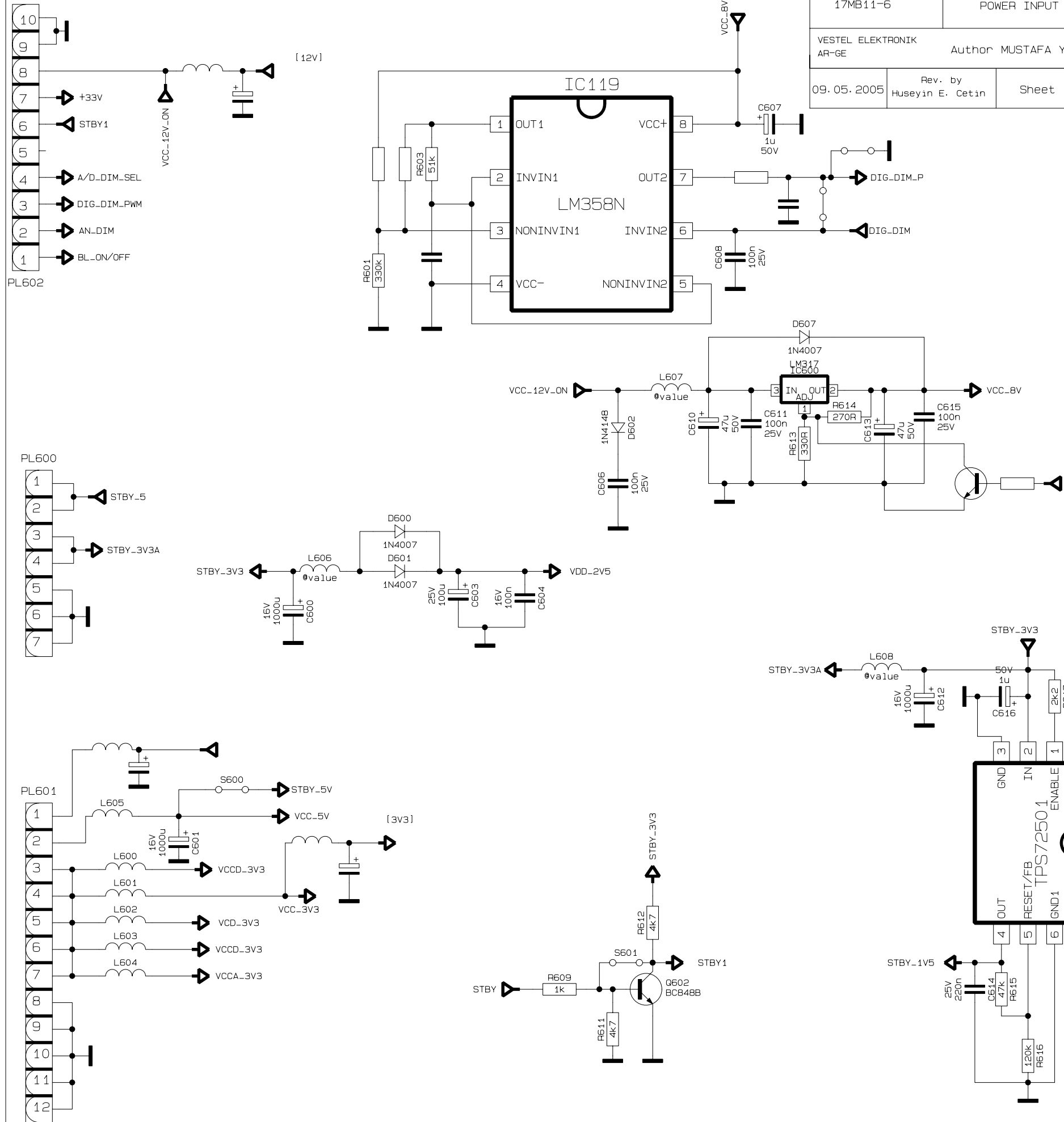
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17MB11-6	DVI RECEIVER SIL151B		
Rev. by Huseyin E. Cetin	09.05.2005	Author MUSTAFA YATIR VESTEL R&D MANISA, TURKEY	Sheet 05

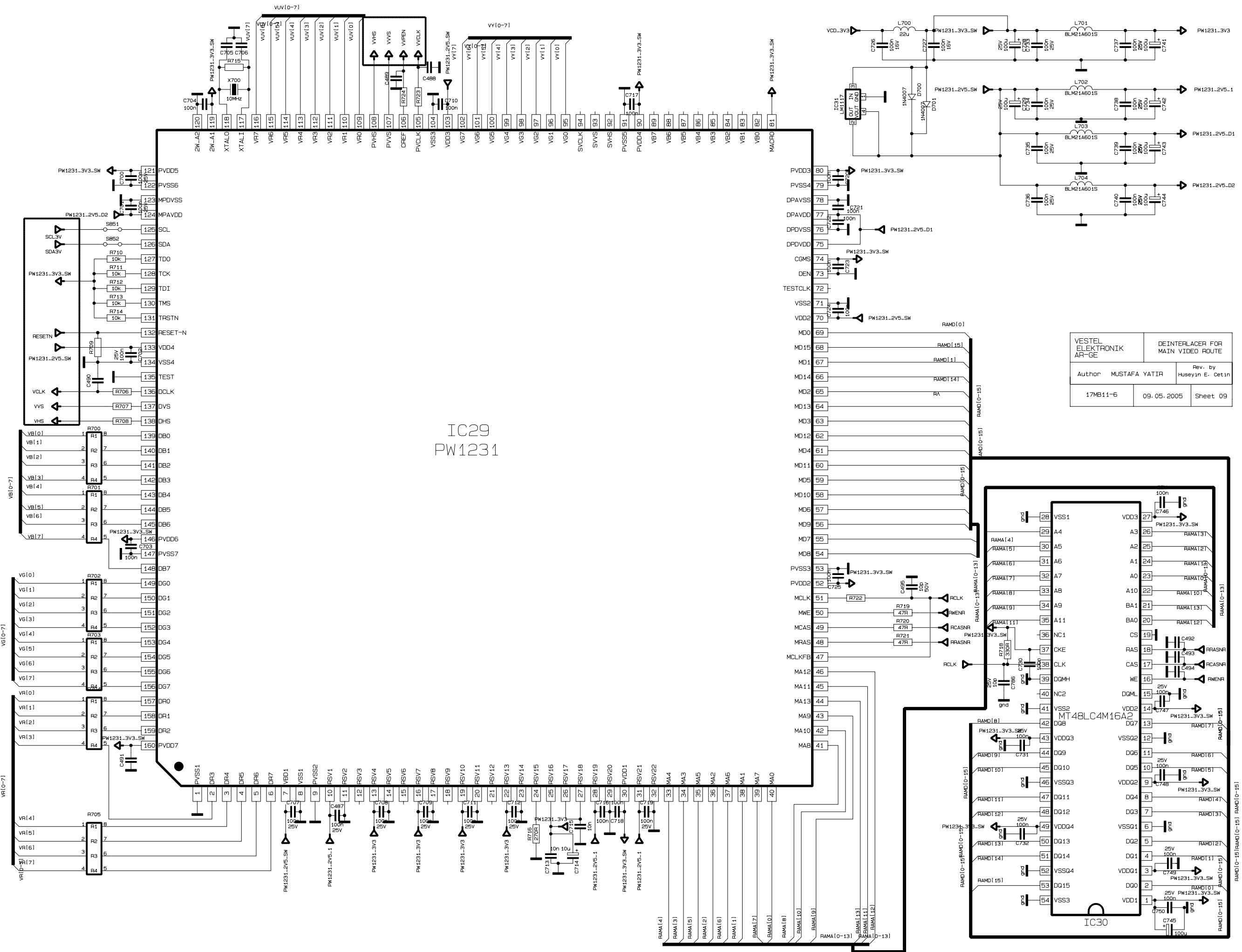
5-PIN PROTECT SINYALI ICIN OPSİYON

PL602

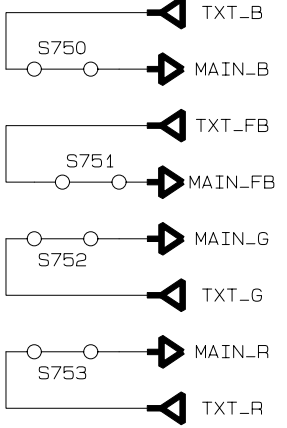
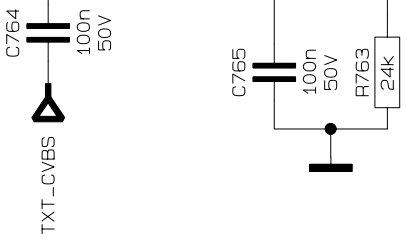
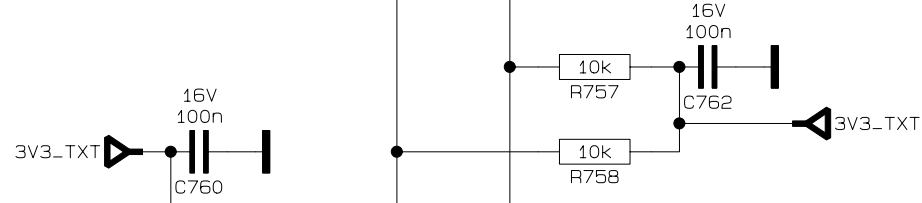
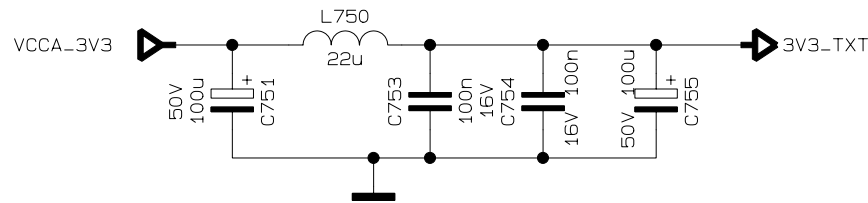
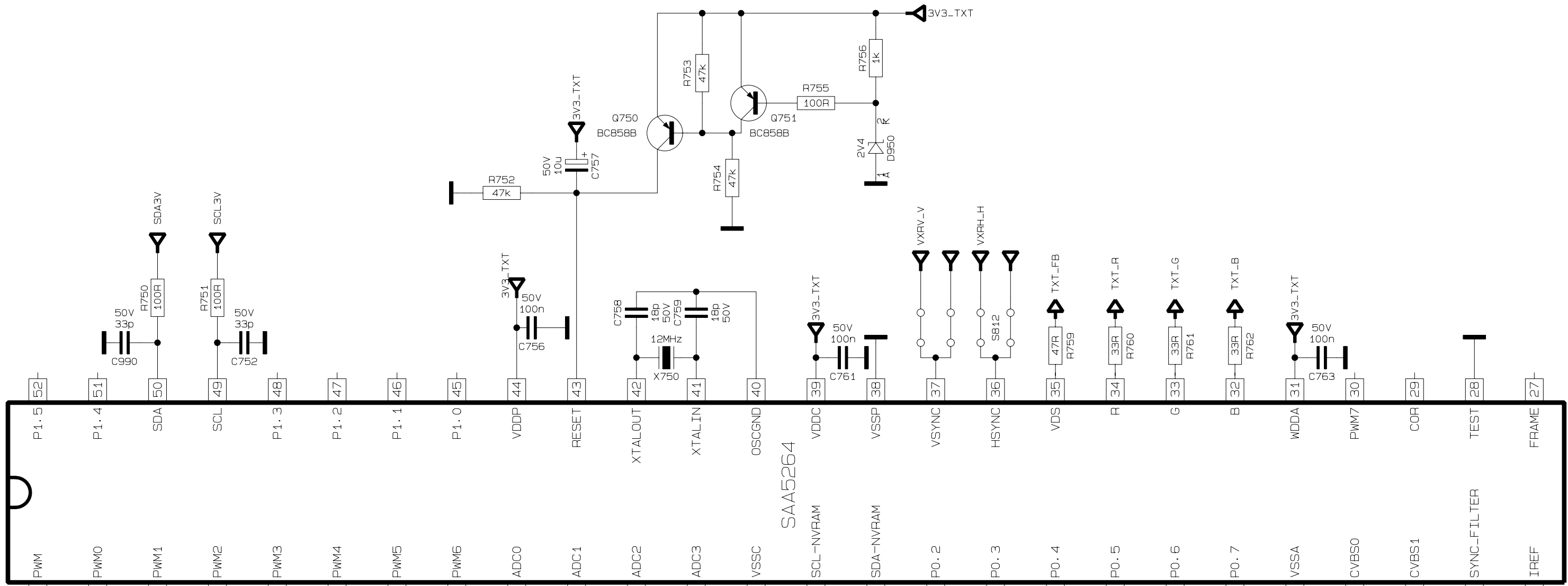
PL600

PL601

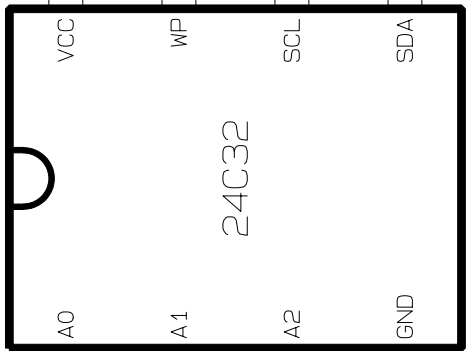




IC32



IC33



VESTEL ELEKTRONIK AR-GE			
17MB11-6	TELETEXT DECODER		
Rev. by Huseyin E. Cetin	09. 05. 2005	Author MUSTAFA YATIR VESTEL R&D MANISA, TURKEY	Sheet 10

